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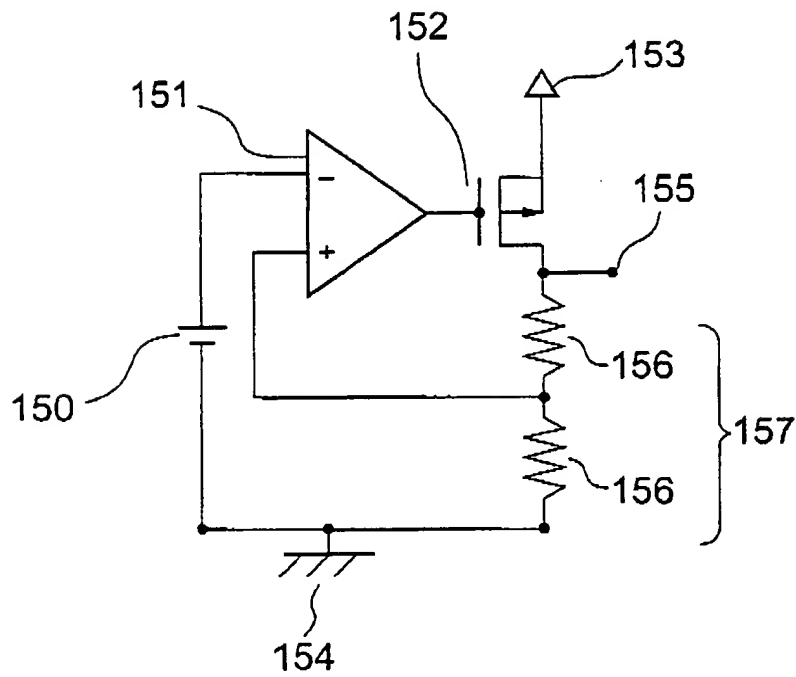


FIG.3

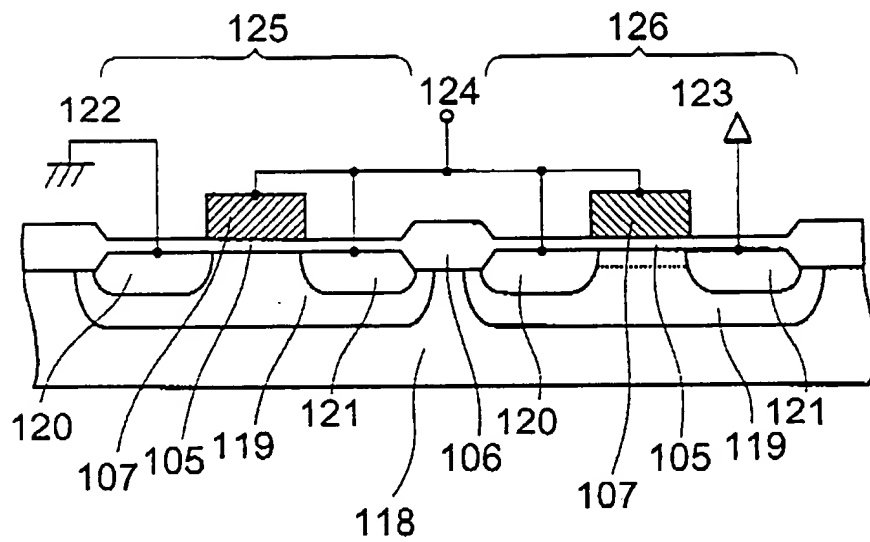


FIG. 4

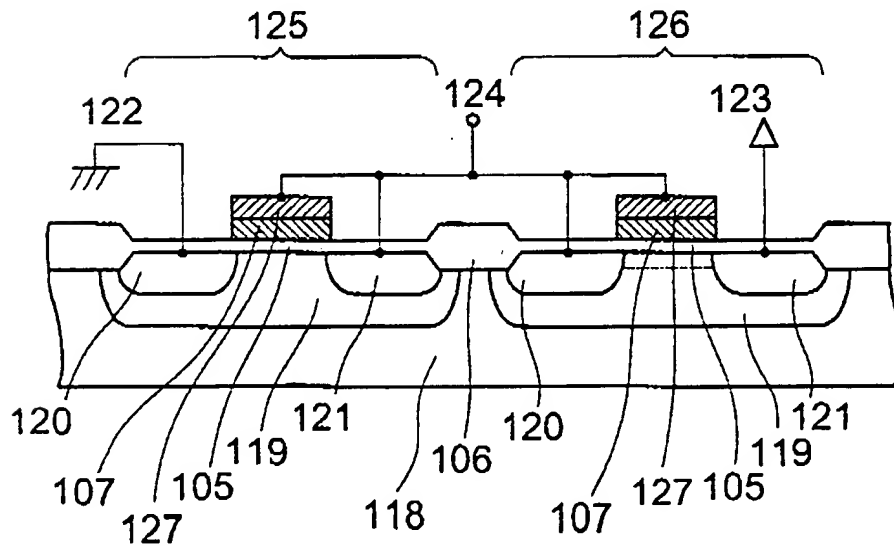


FIG. 5

FIG. 4

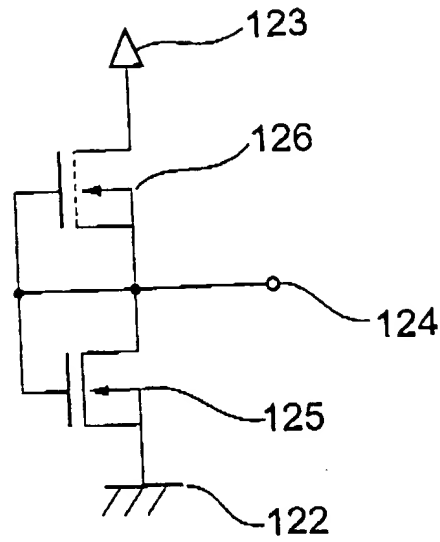


FIG. 6

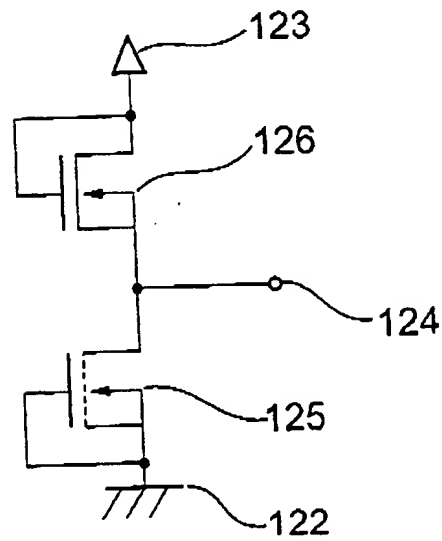


FIG. 7

FIG. 6

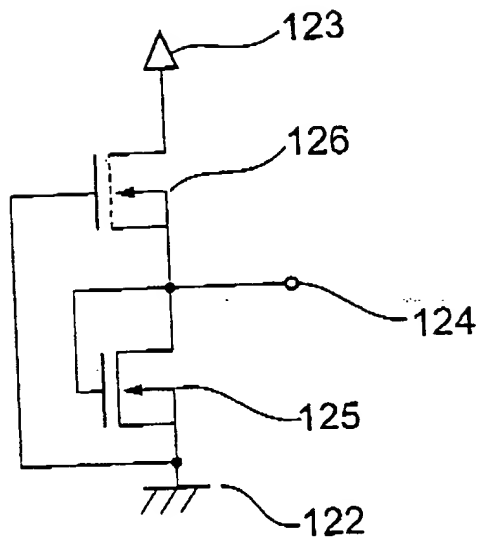


FIG.8

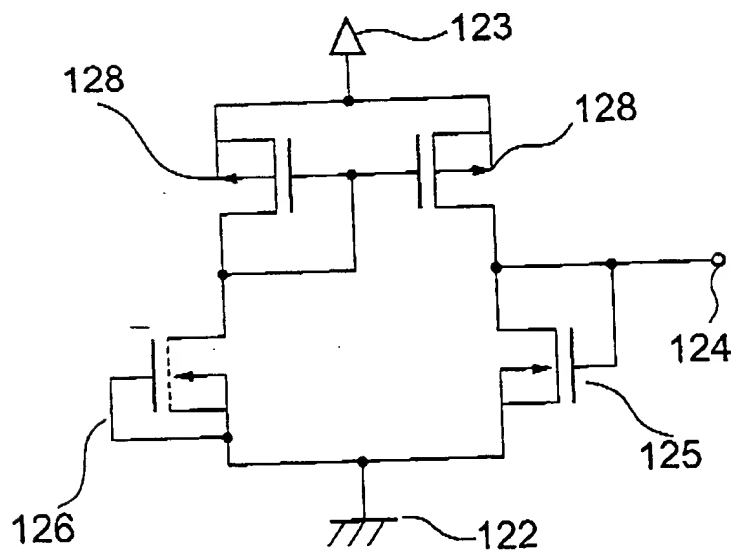


FIG.9

TOP SECRET

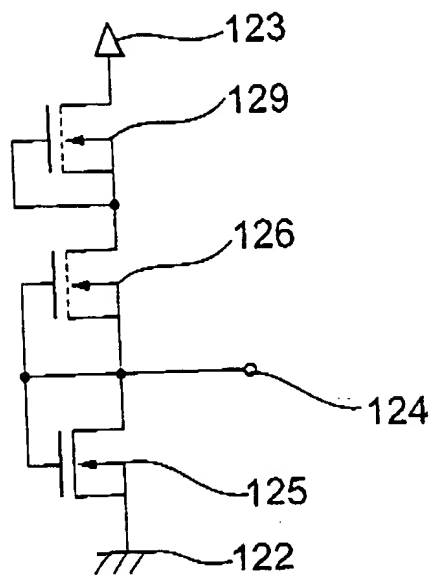


FIG.10

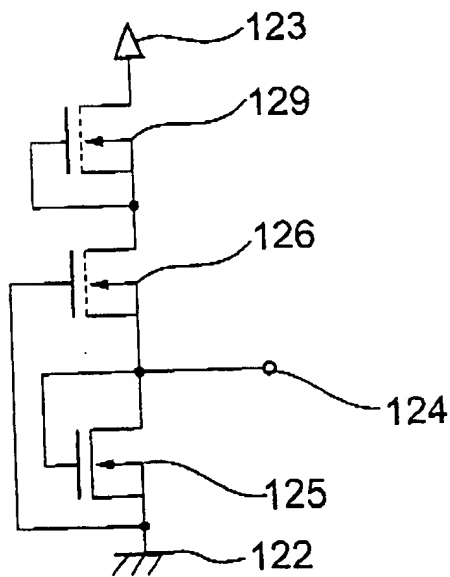


FIG.11

TOP SECRET

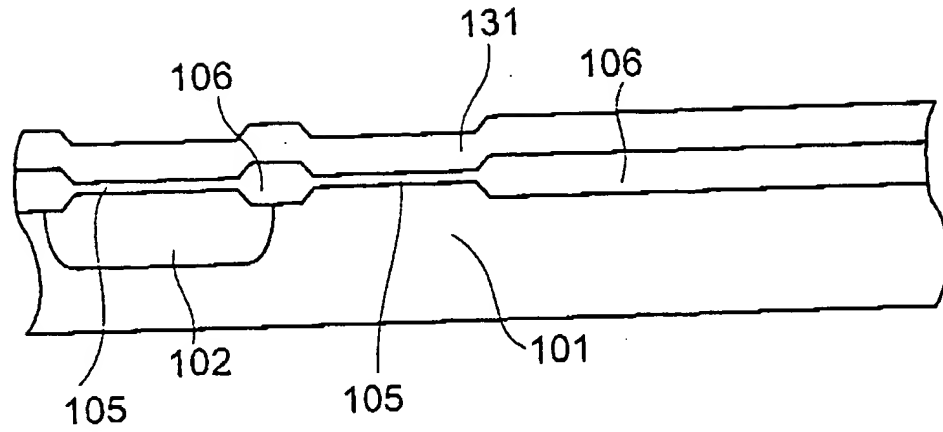


FIG.12

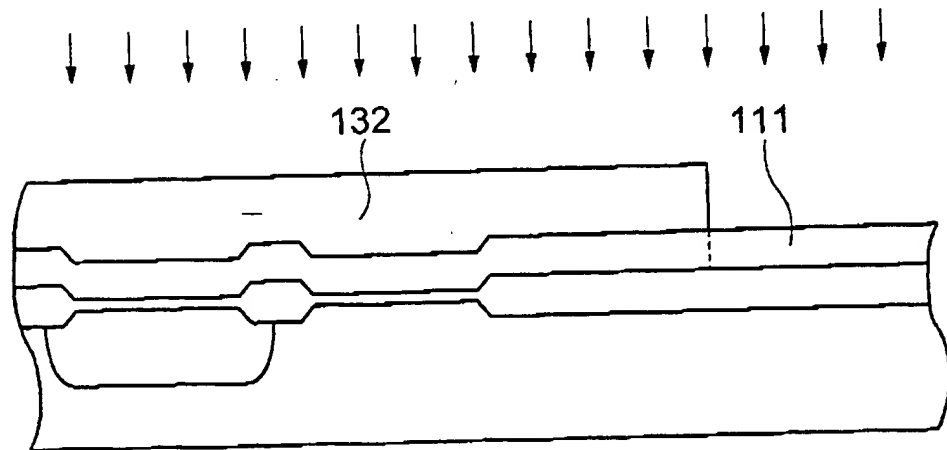


FIG.13

FIG. 12

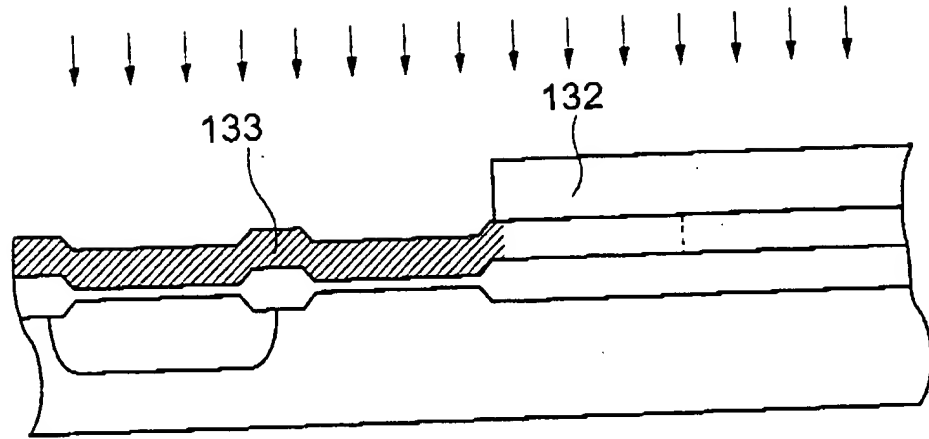


FIG.14

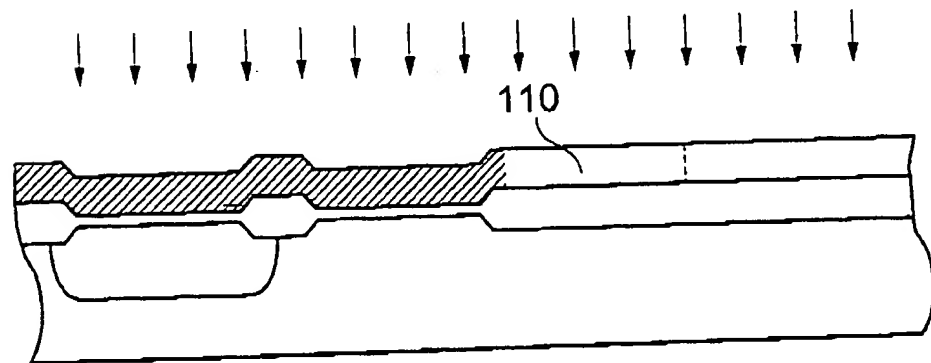


FIG.15

FIG. 14

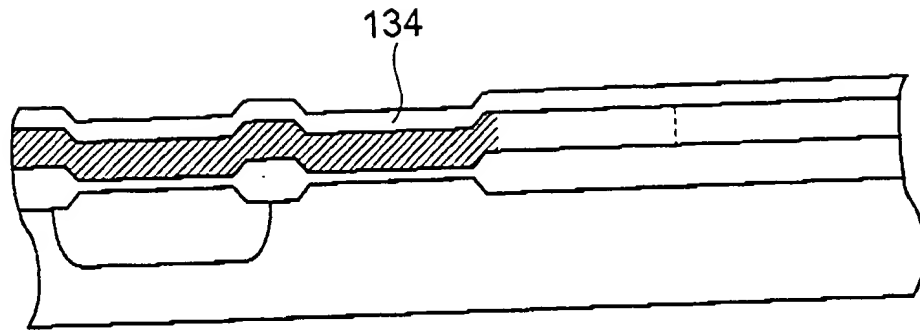


FIG. 16

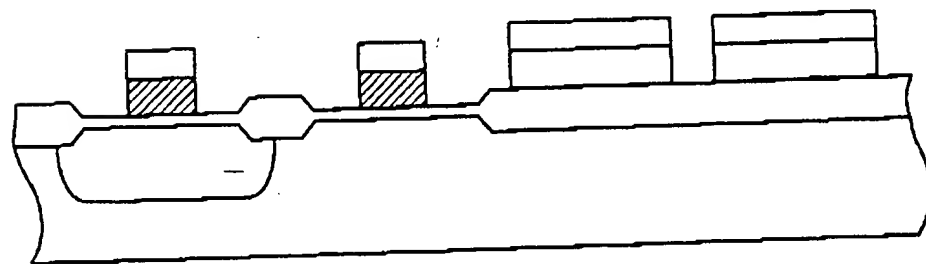


FIG. 17

FIG. 16

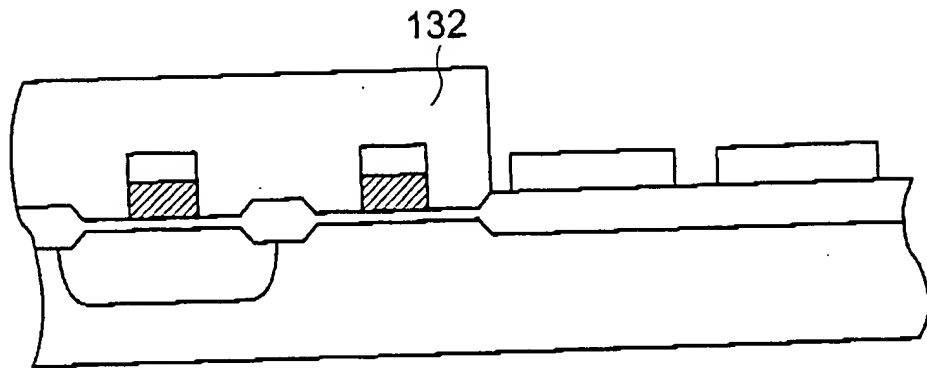


FIG. 18

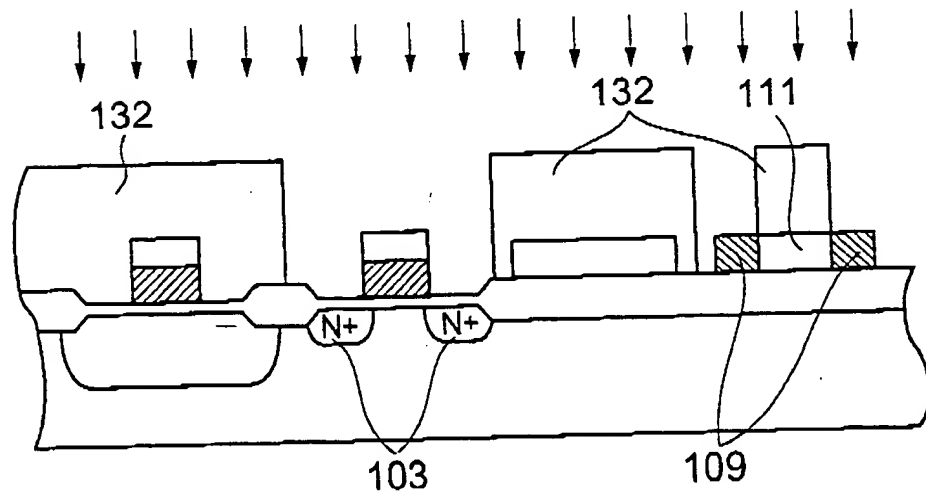


FIG. 19

FIG. 18

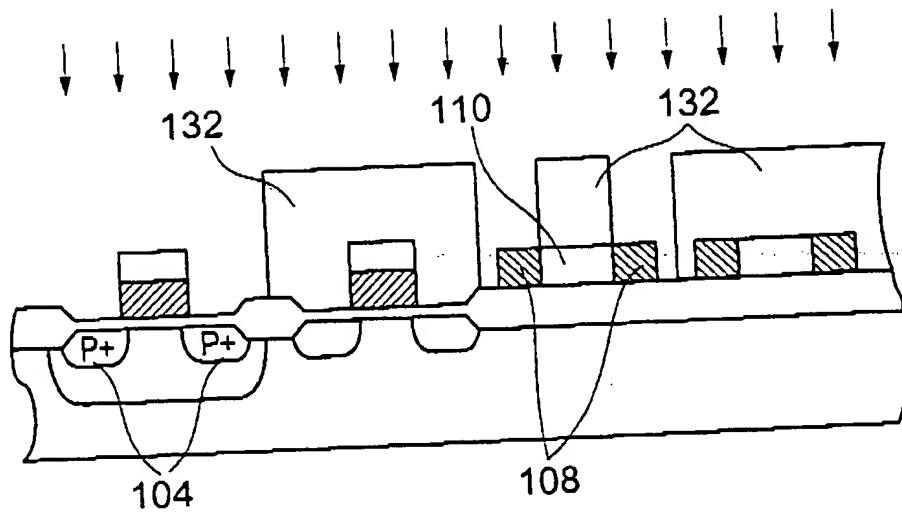


FIG.20

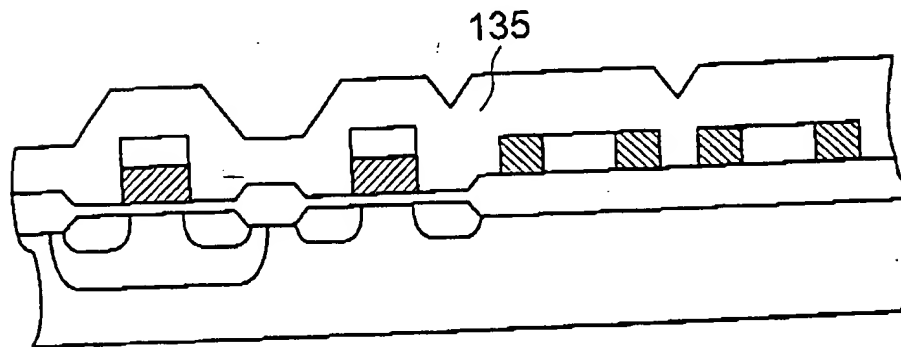


FIG.21

TOP SECRET

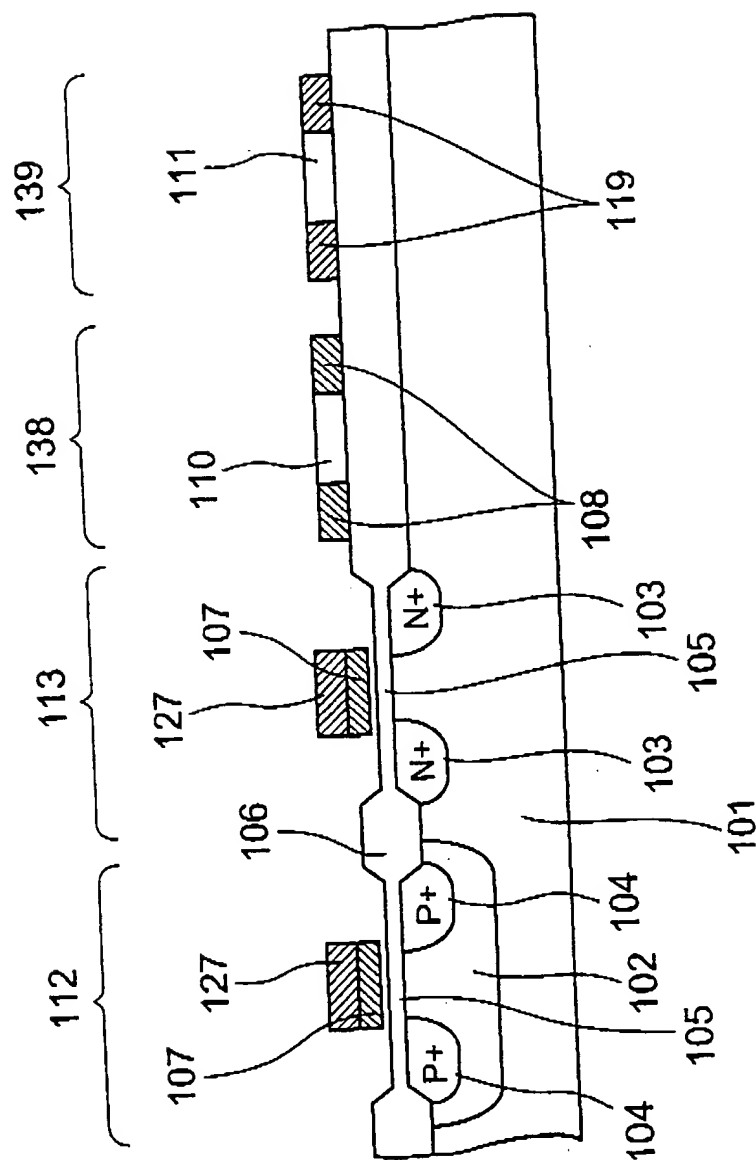


FIG. 22

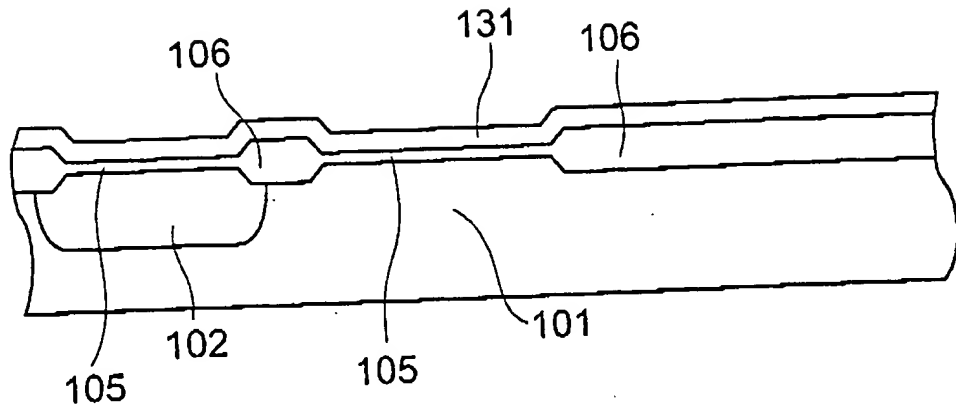


FIG.23

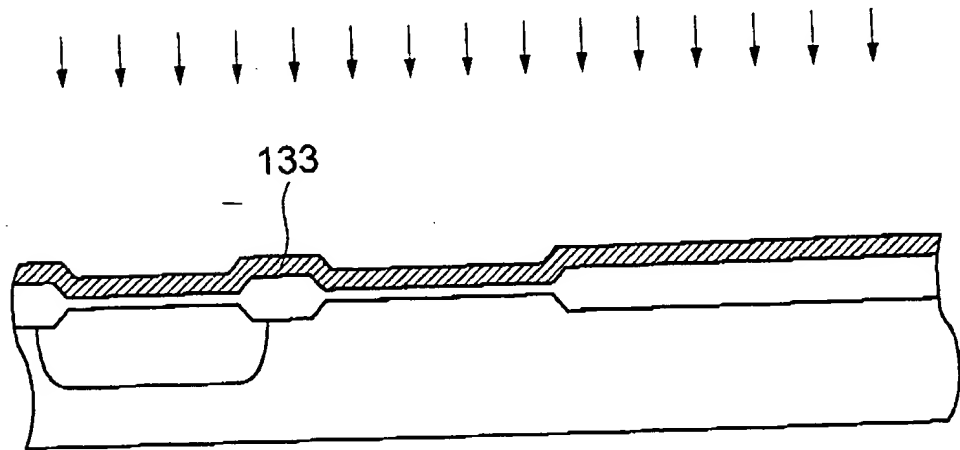


FIG.24

FIG. 23

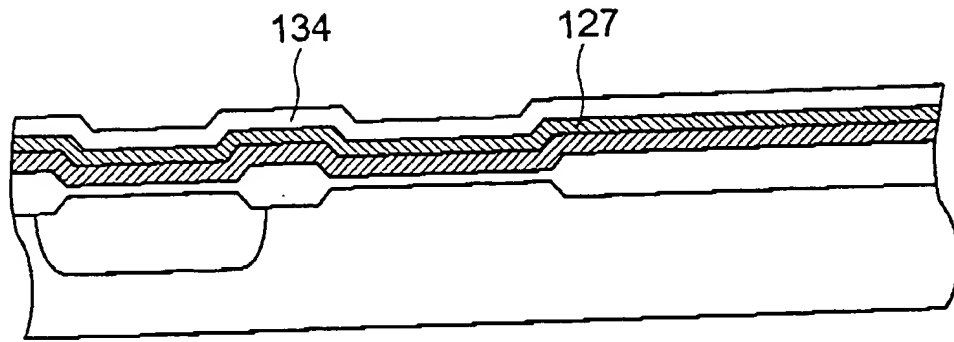


FIG.25

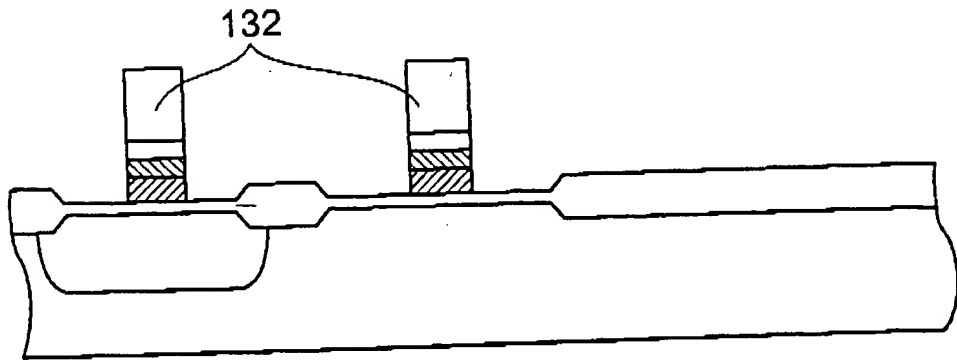


FIG.26

FIG. 25

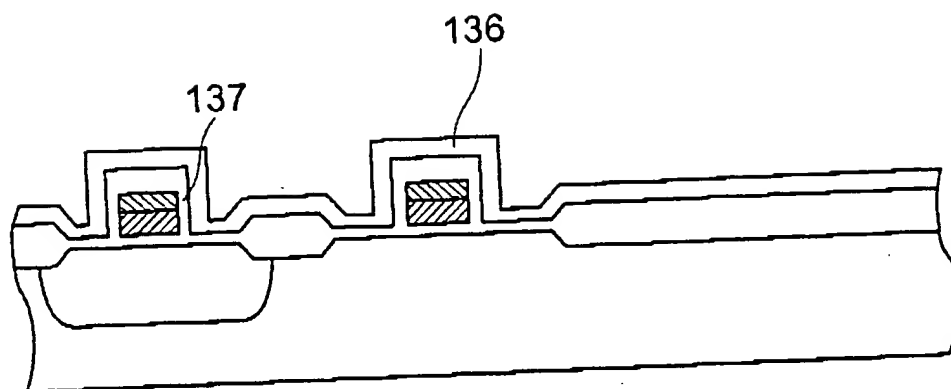


FIG.27

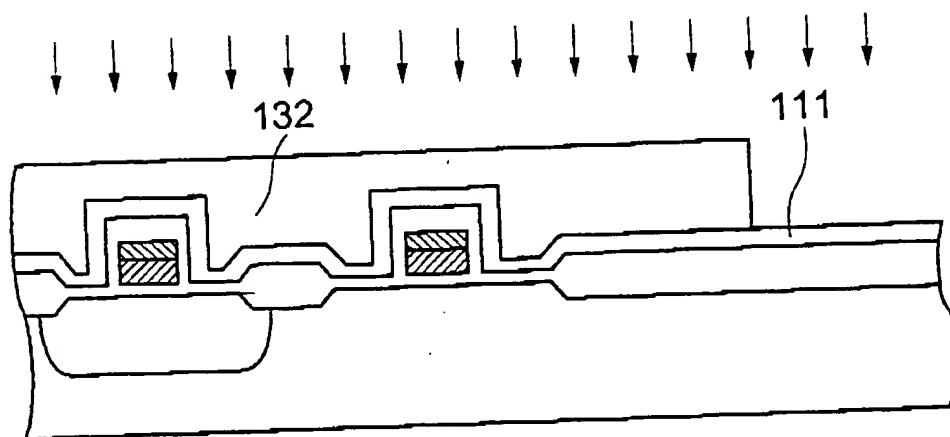


FIG.28

FIG. 27

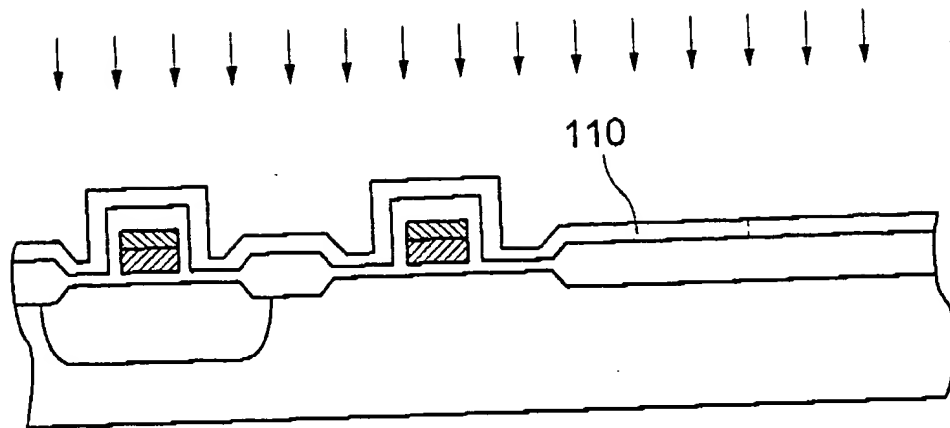


FIG. 29

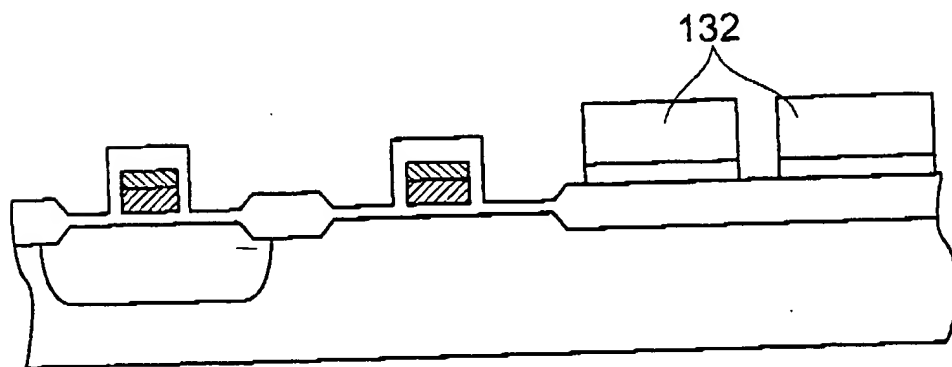


FIG. 30

FIG. 29

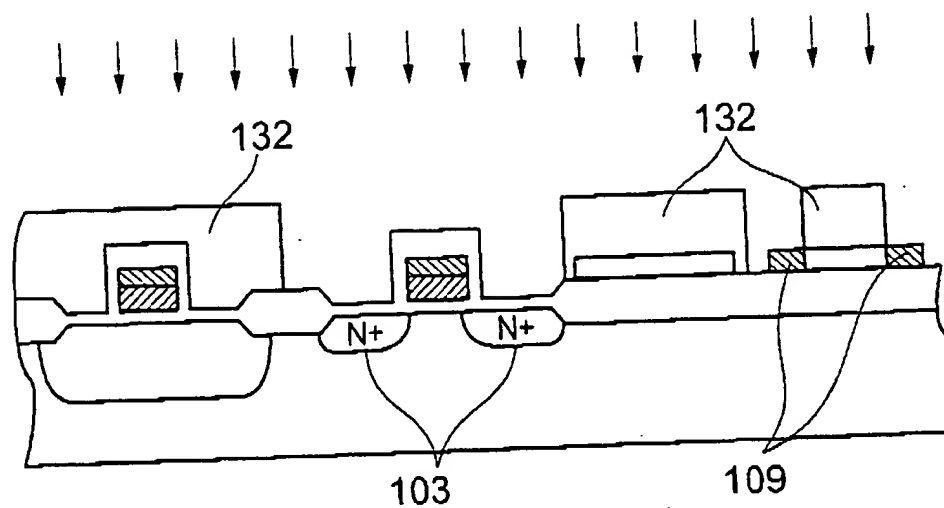


FIG.31

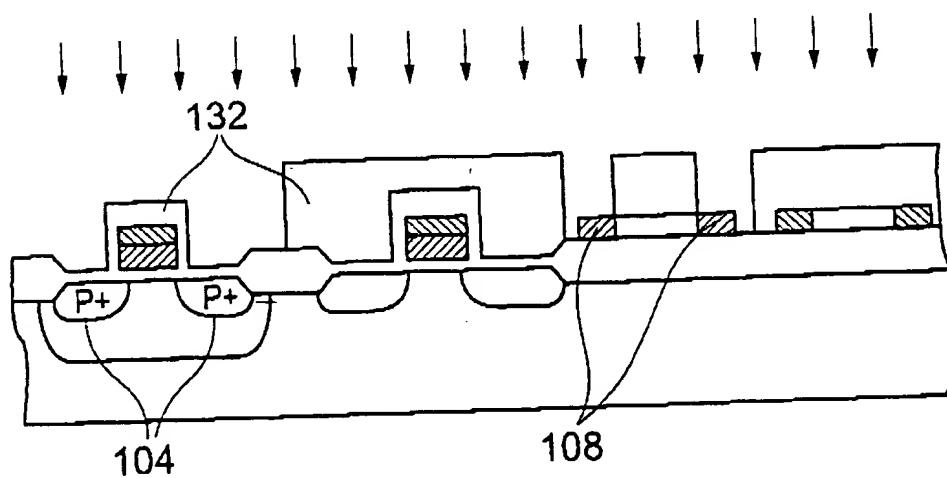


FIG.32

TOP SECRET

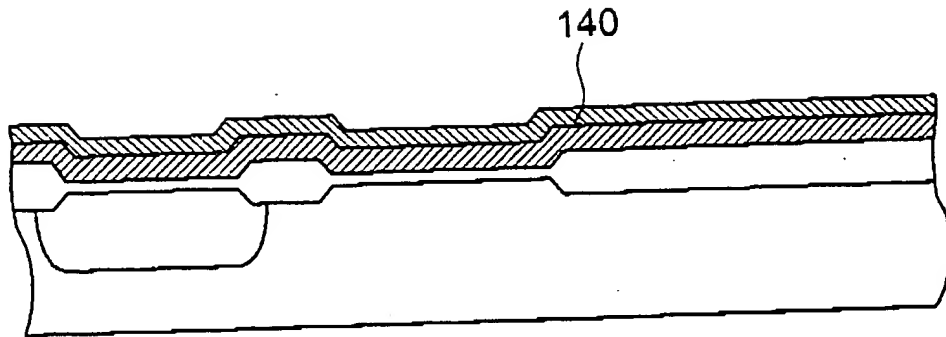


FIG.33

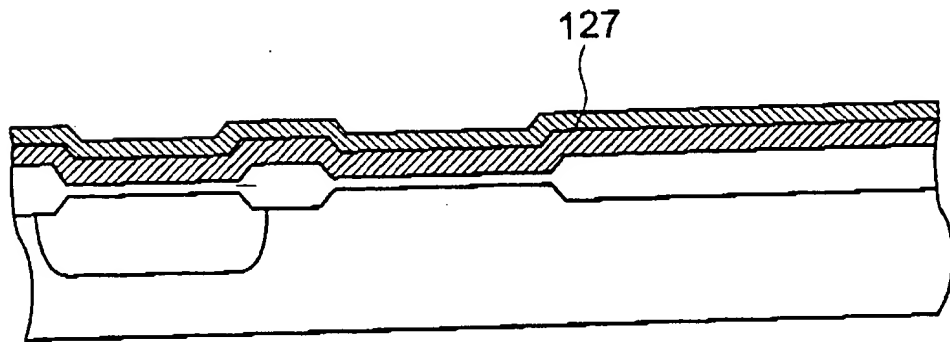


FIG.34

TOP SECRET

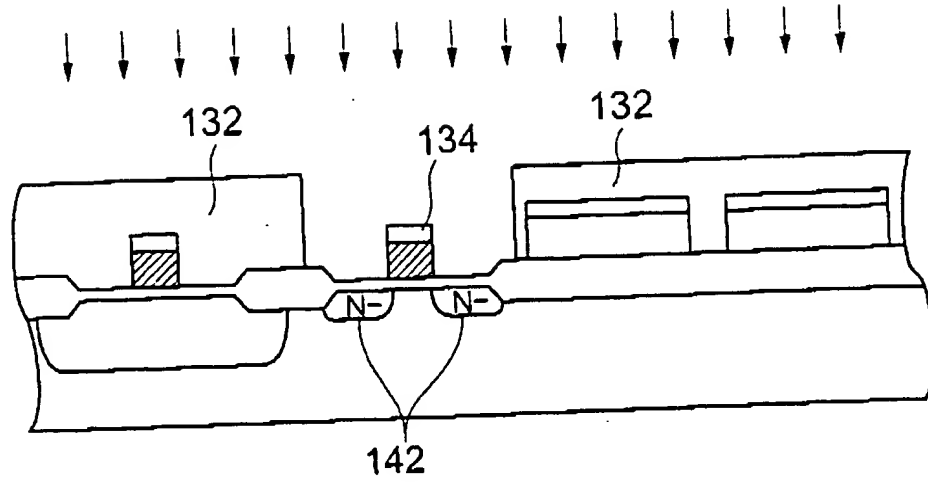


FIG.36

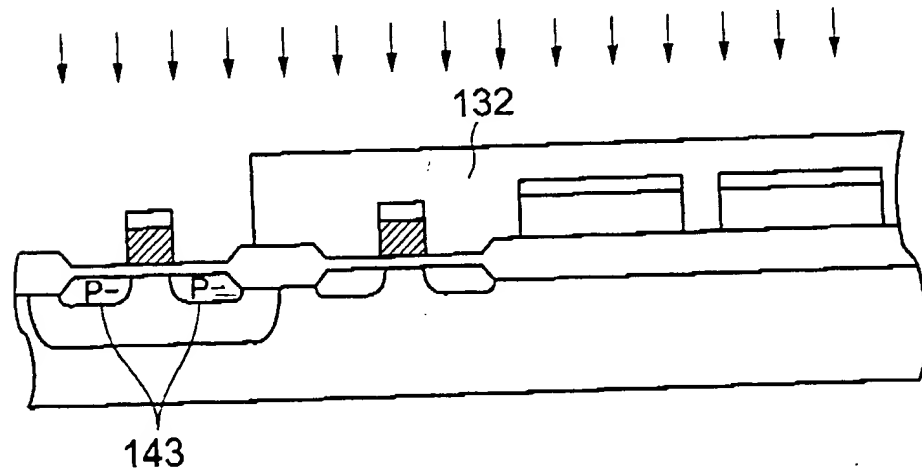


FIG.37

FIG. 36

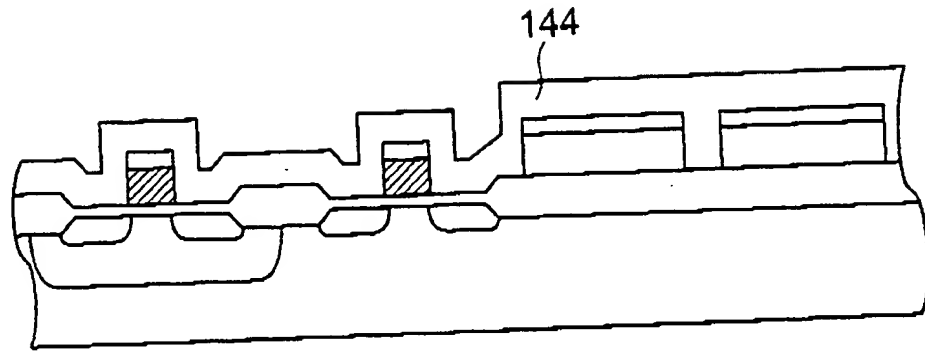


FIG. 38

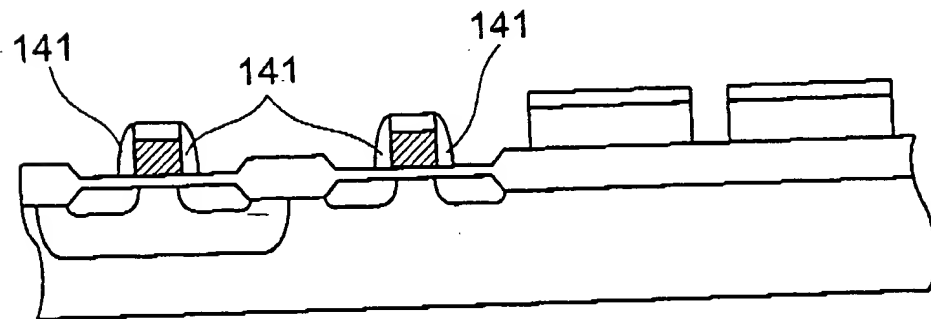


FIG. 39

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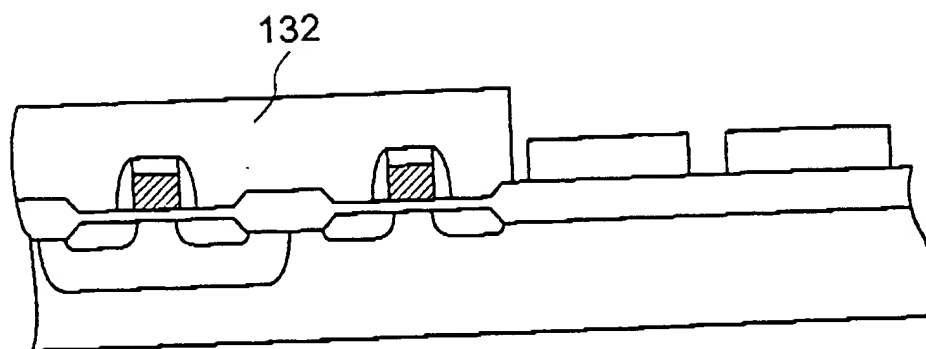


FIG. 40

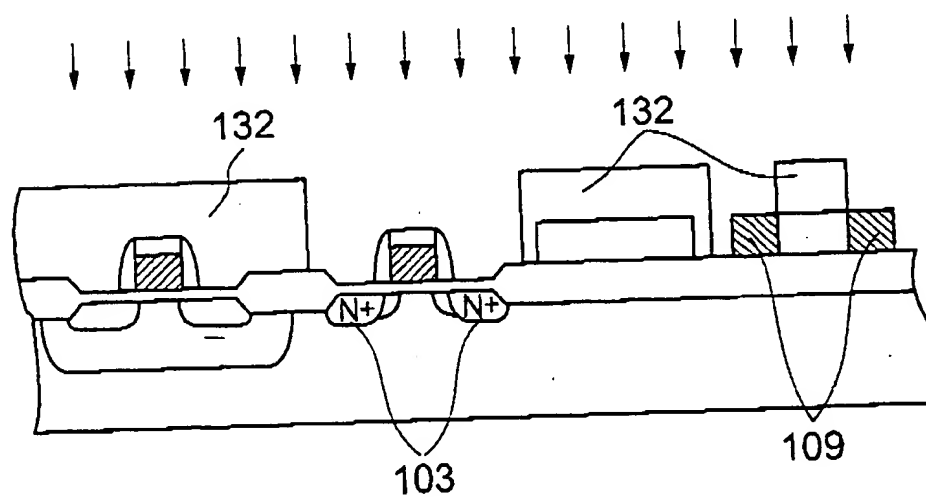


FIG. 41

FIG. 40

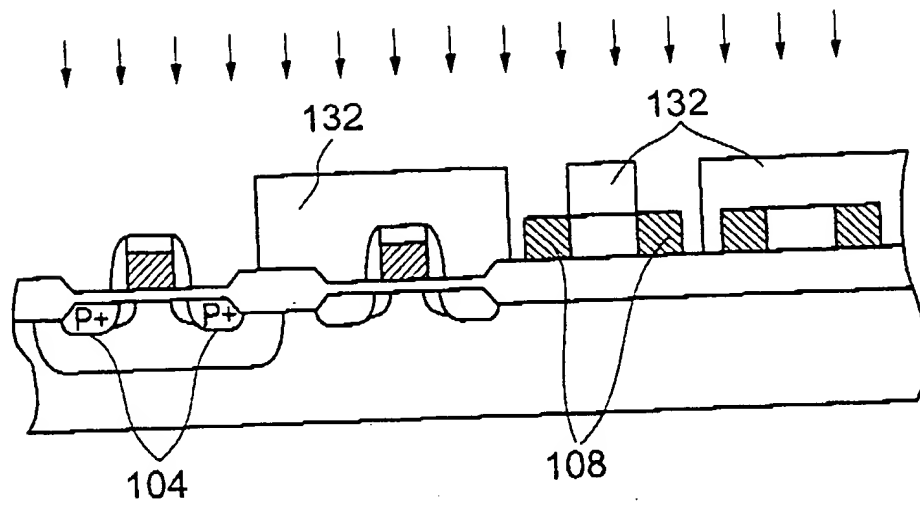


FIG. 42

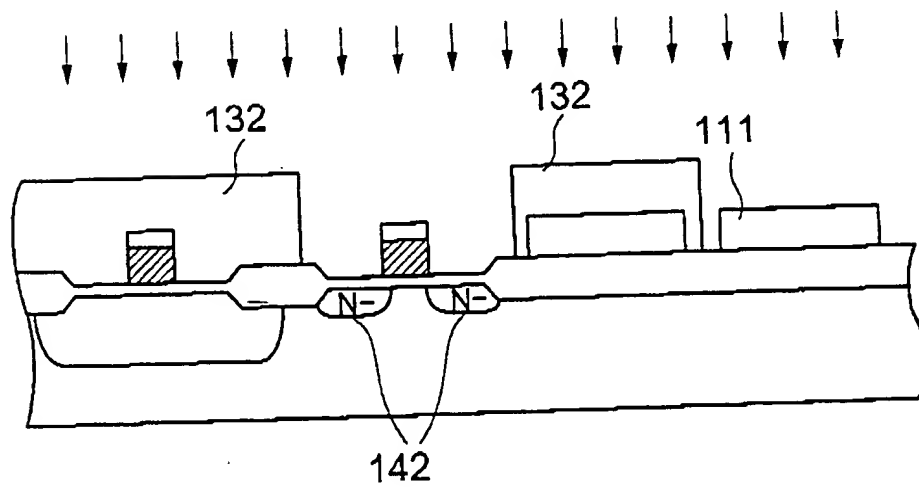


FIG. 43

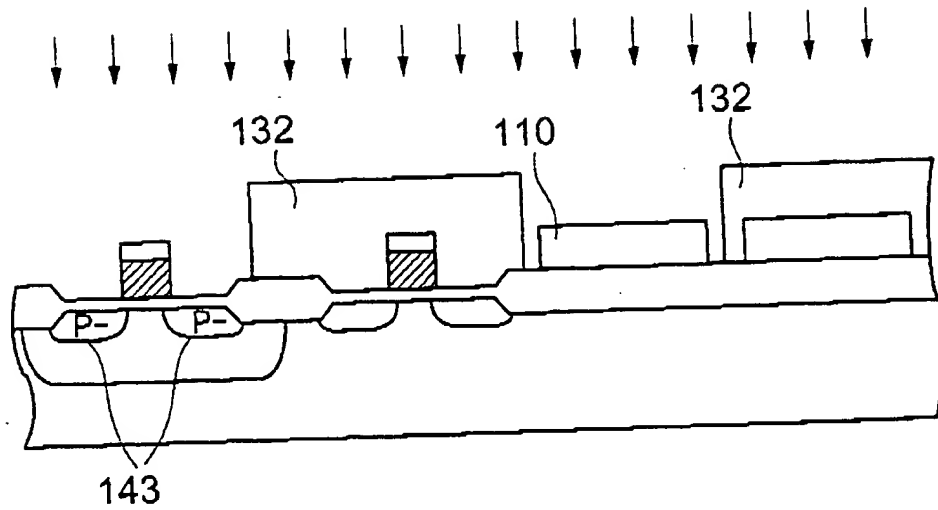


FIG.44

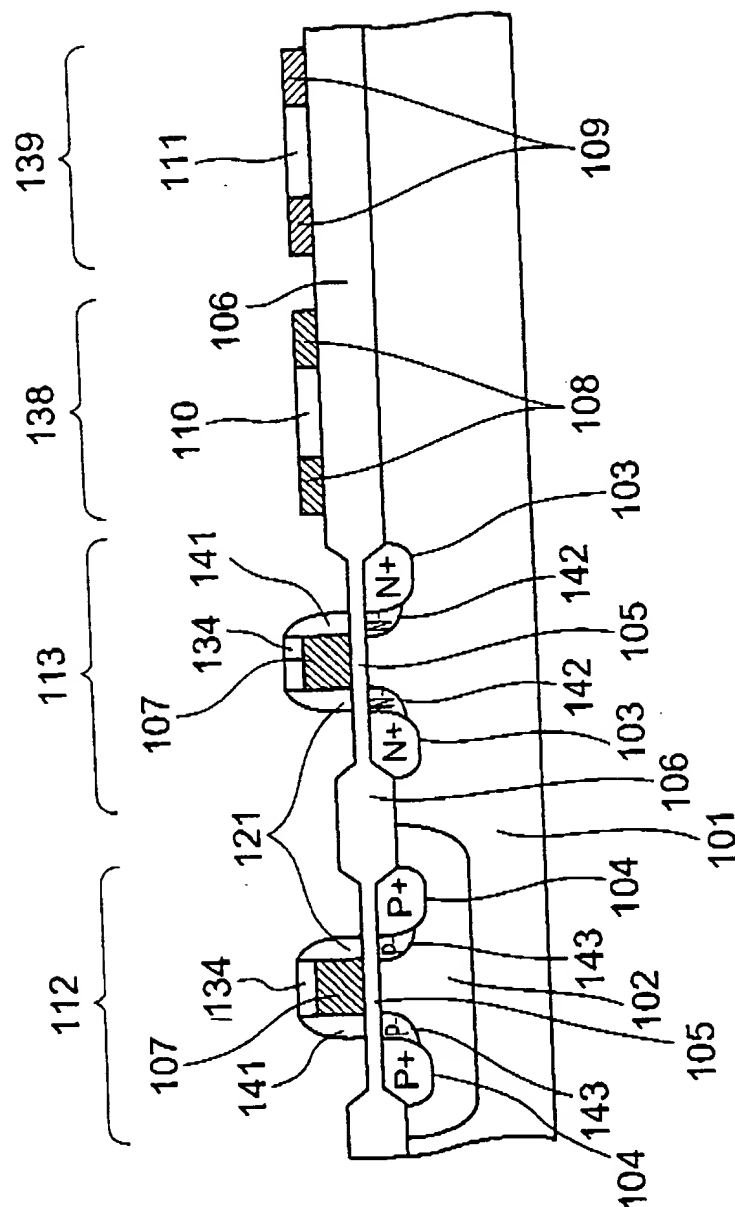


FIG.45

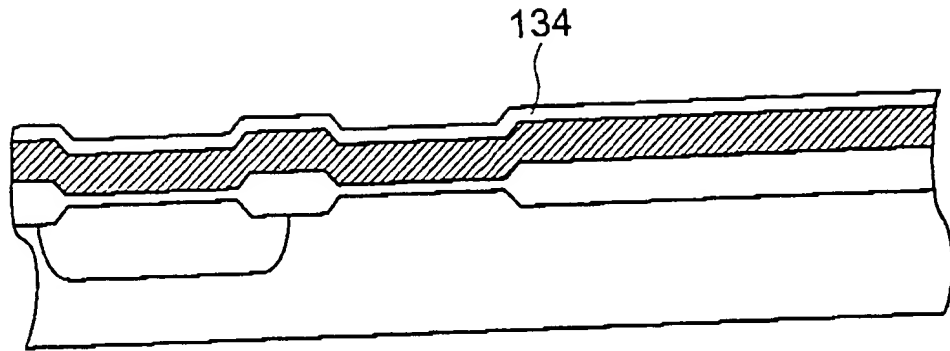


FIG.46

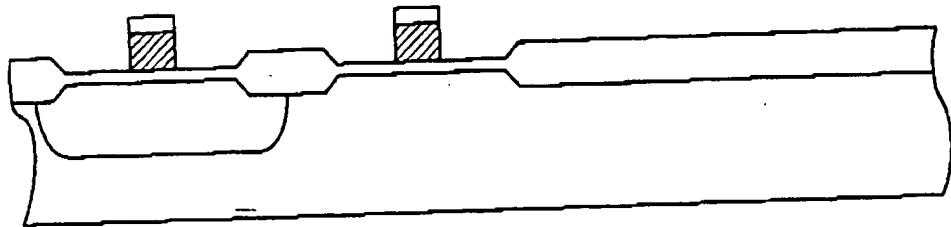


FIG.47

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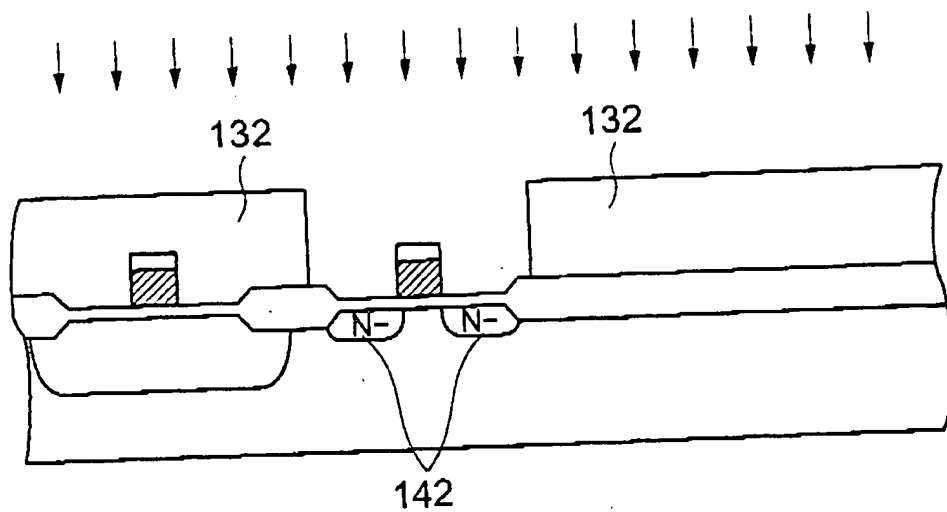


FIG.48

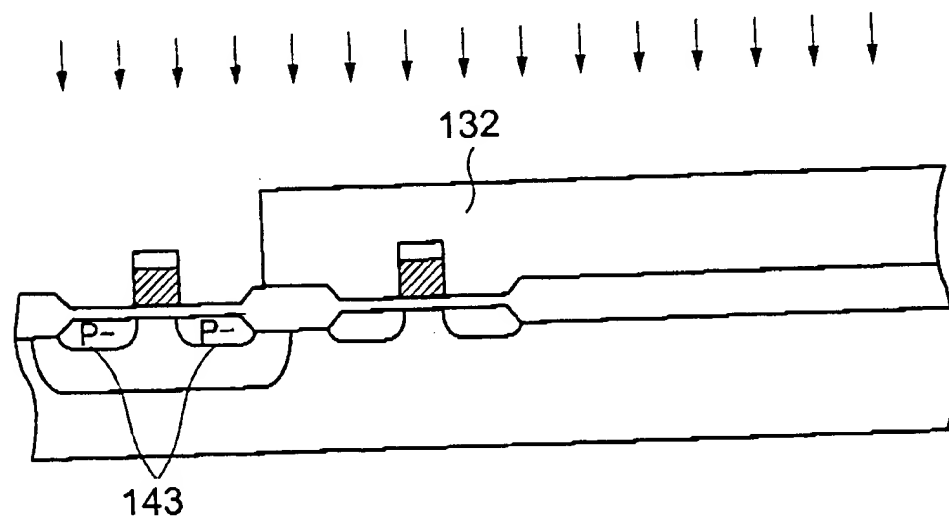


FIG.49

FIG. 48-994660

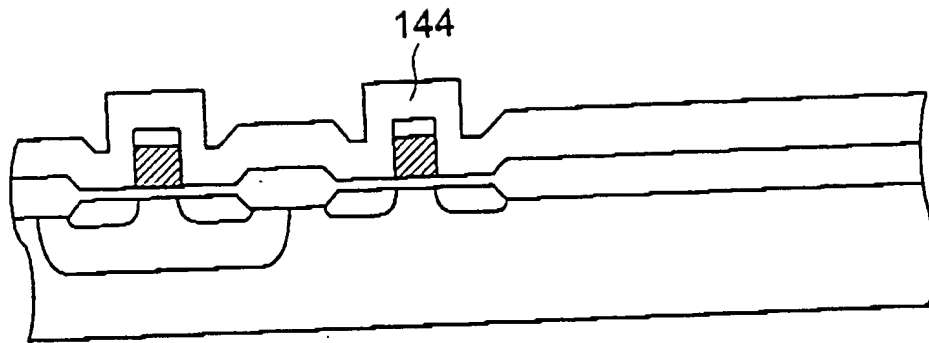


FIG.50

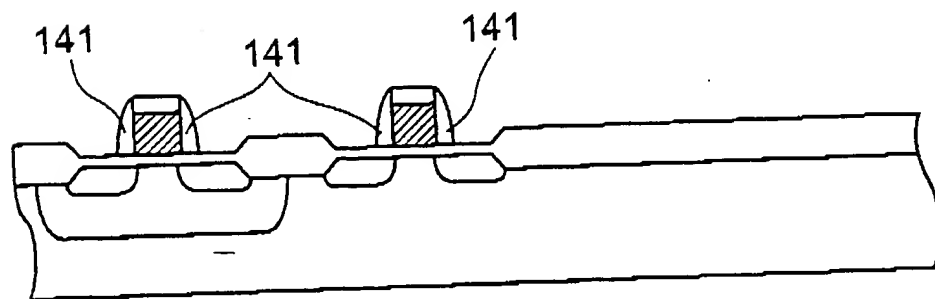


FIG.51

FIG. 50-51

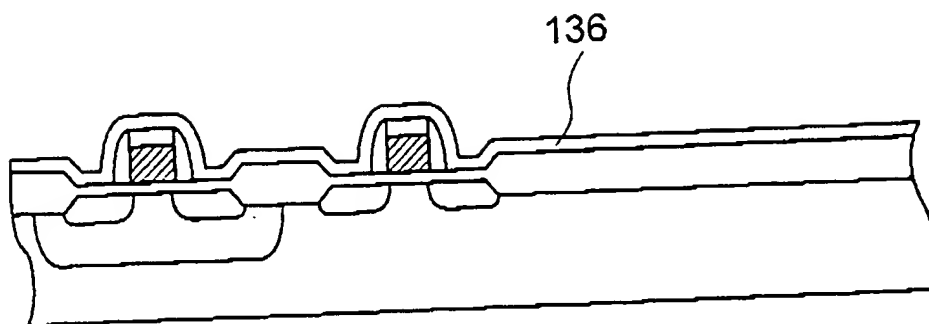


FIG.52

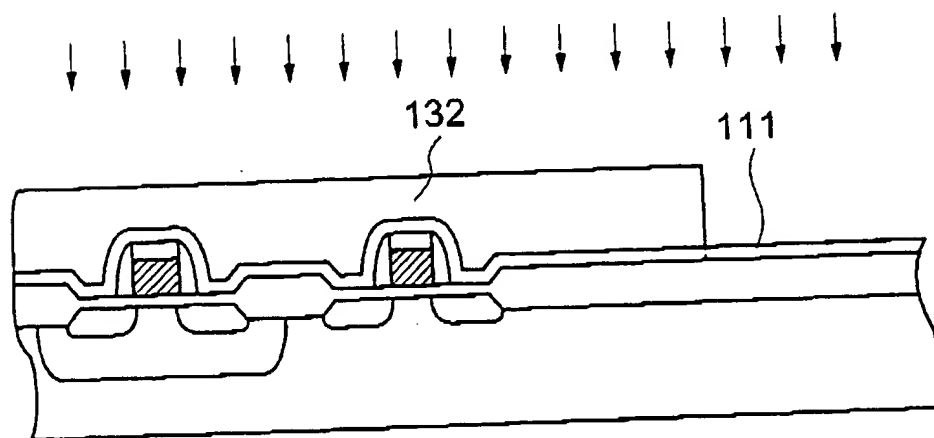


FIG.53

FIG. 52

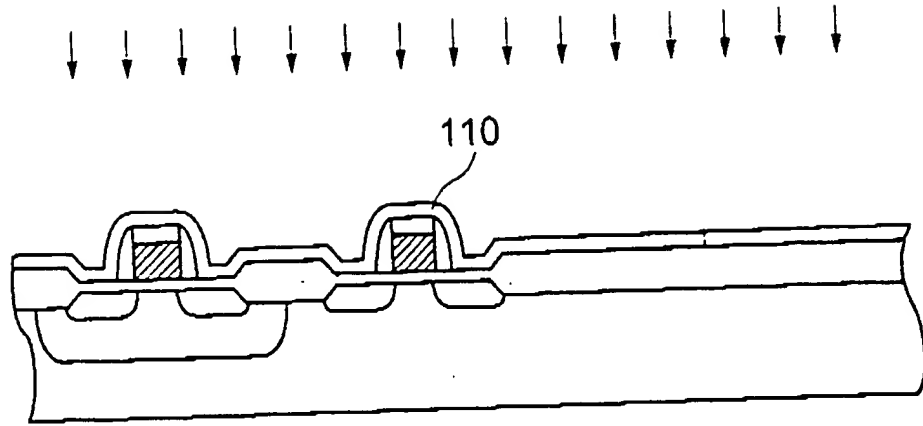


FIG.54

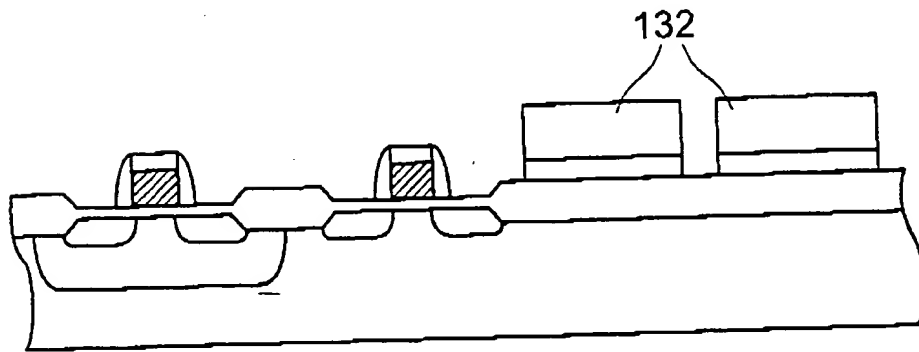


FIG.55

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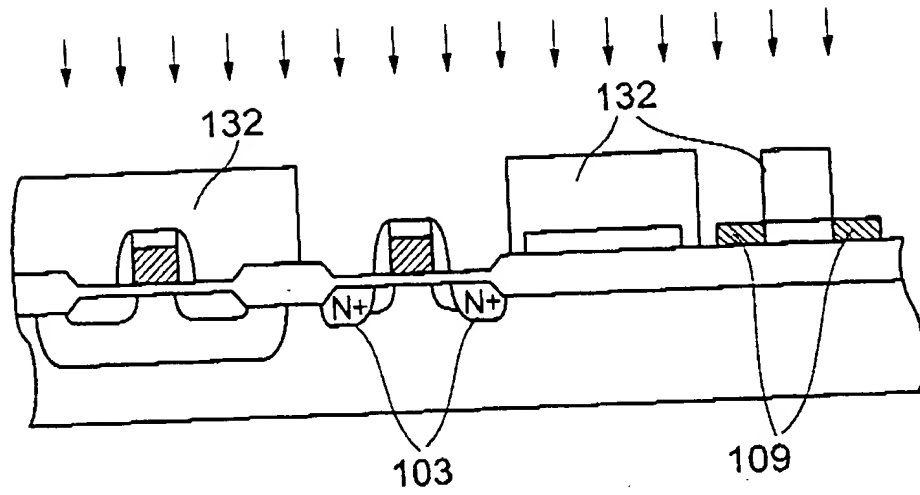


FIG.56

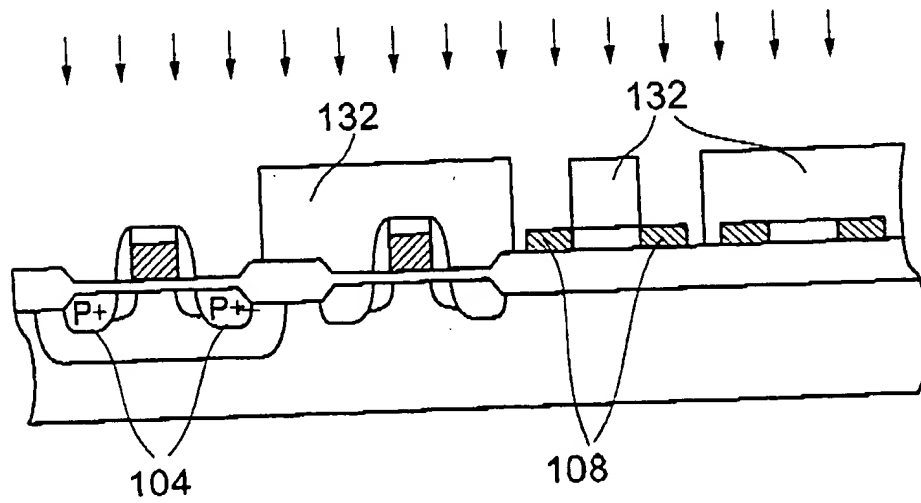


FIG.57

FIG. 56

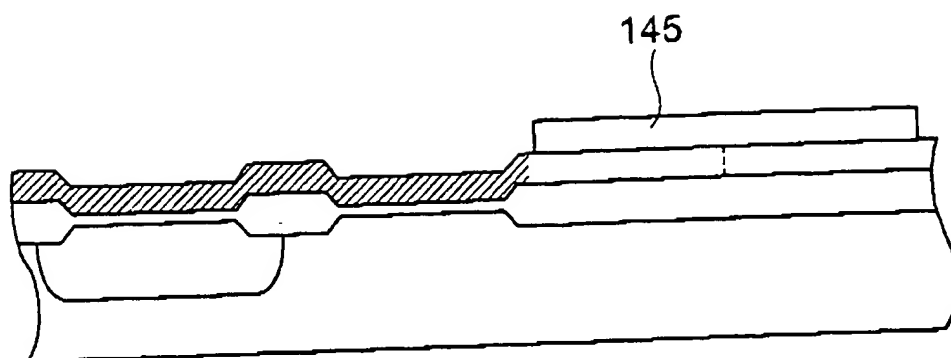


FIG.59

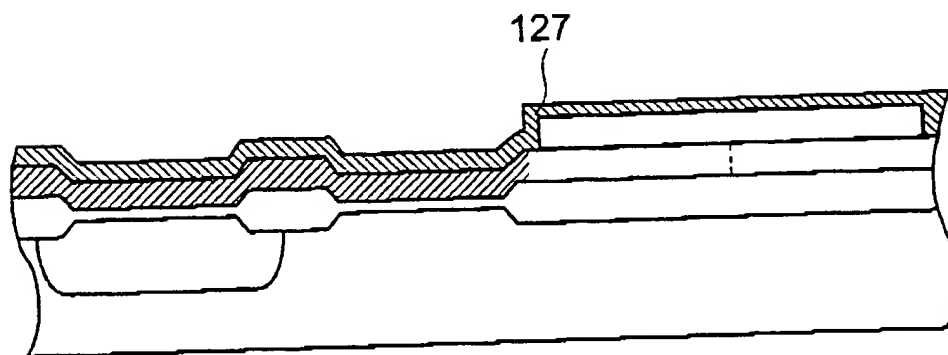


FIG.60

FIG.59

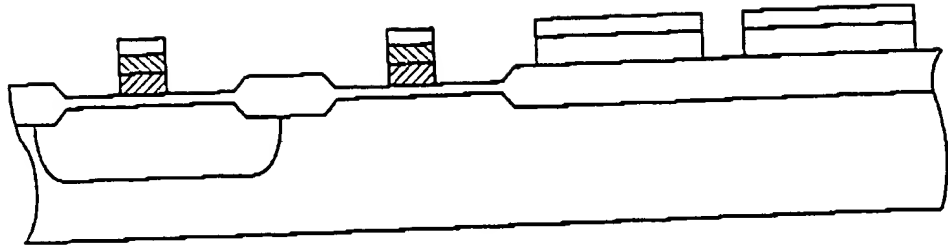


FIG.61

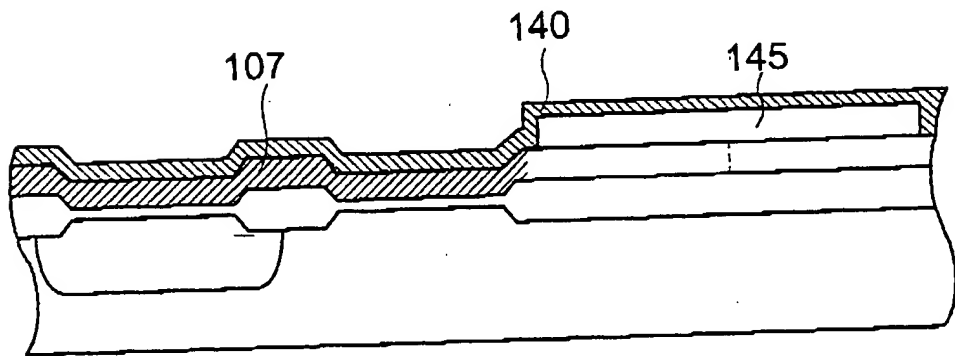


FIG.62

FIG. 61 is a cross-sectional view of a mechanical assembly.

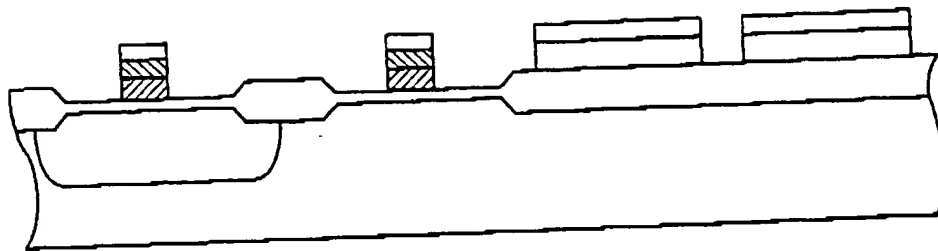


FIG.63

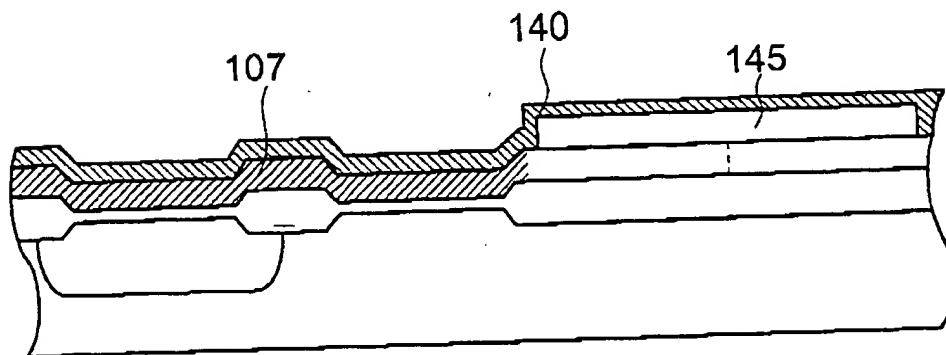


FIG.64

FIG. 63

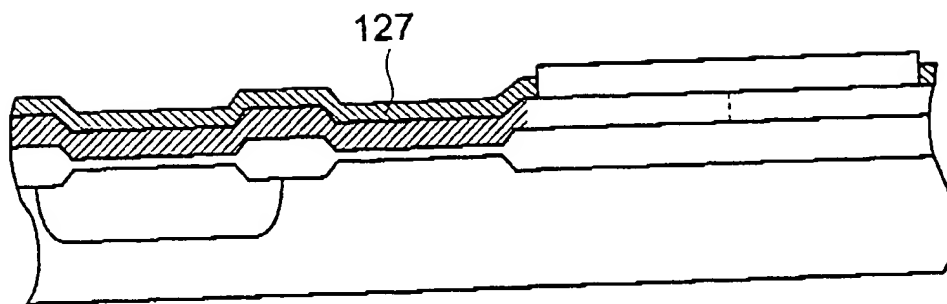


FIG.65

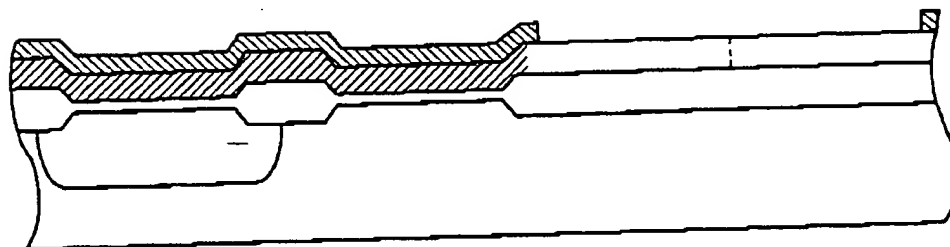


FIG.66

FIG. 65 is a cross-sectional view of a mechanical assembly.

FIG. 68

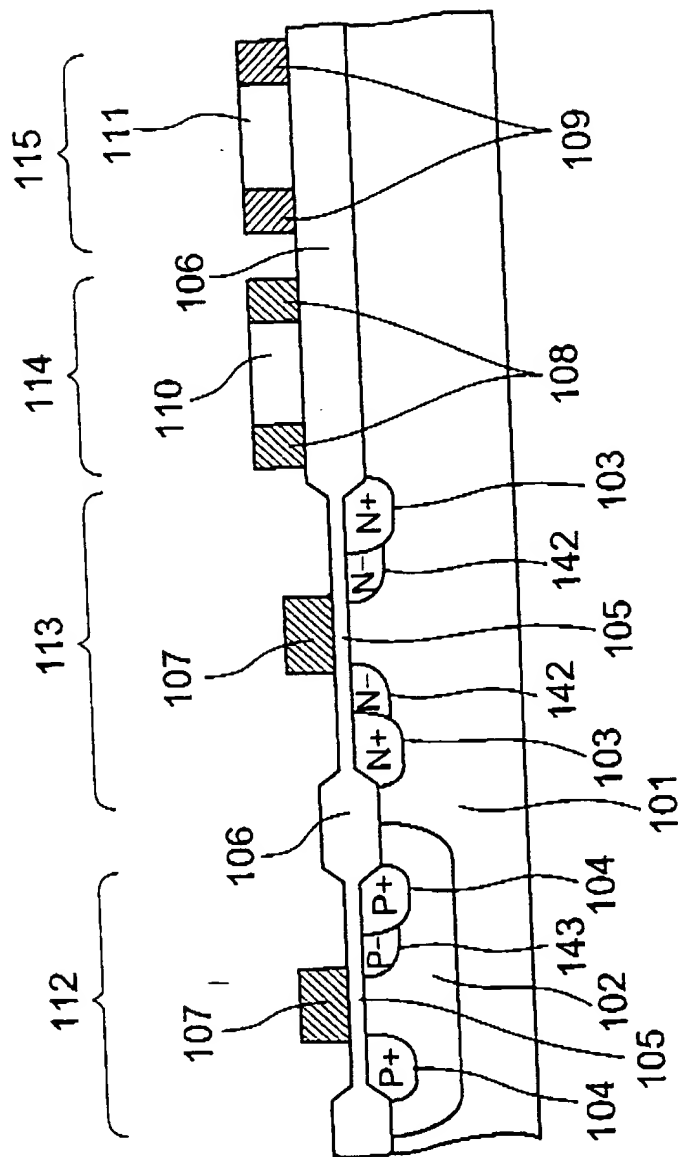


FIG. 68

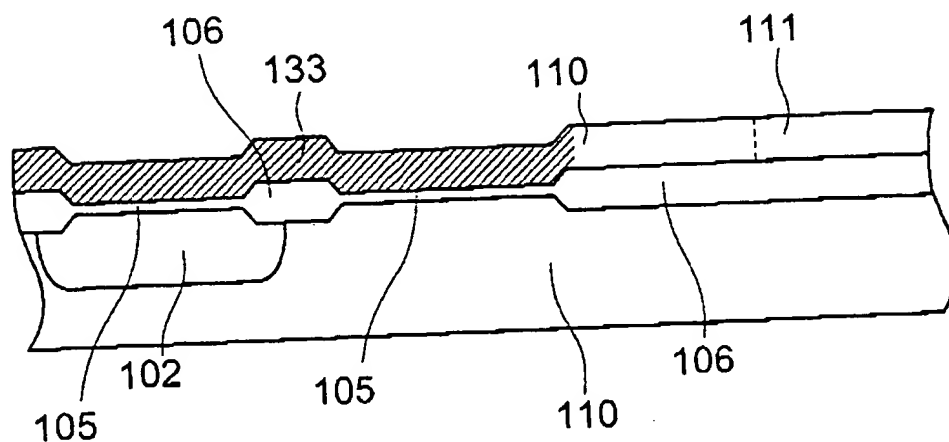


FIG.69

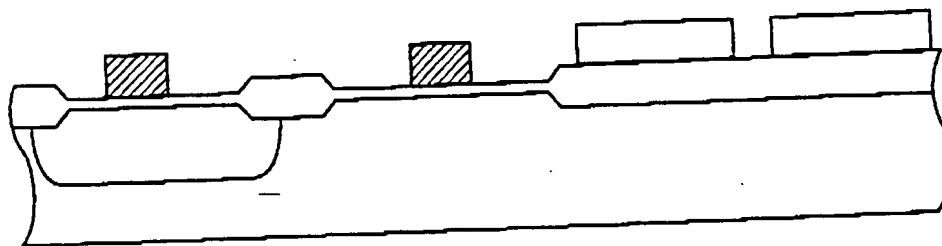


FIG.70

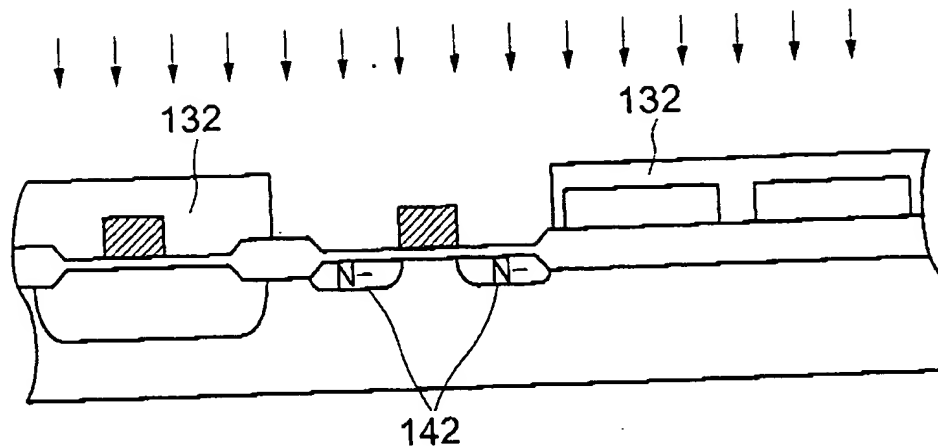


FIG.71

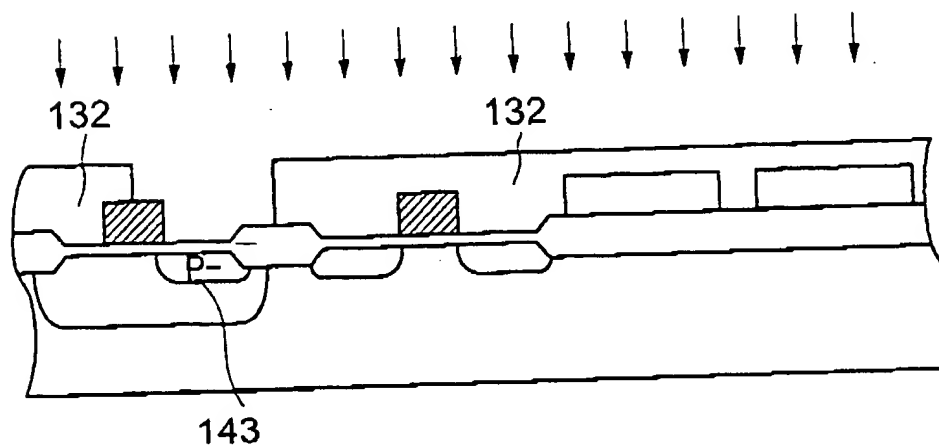


FIG.72

FIG. 71

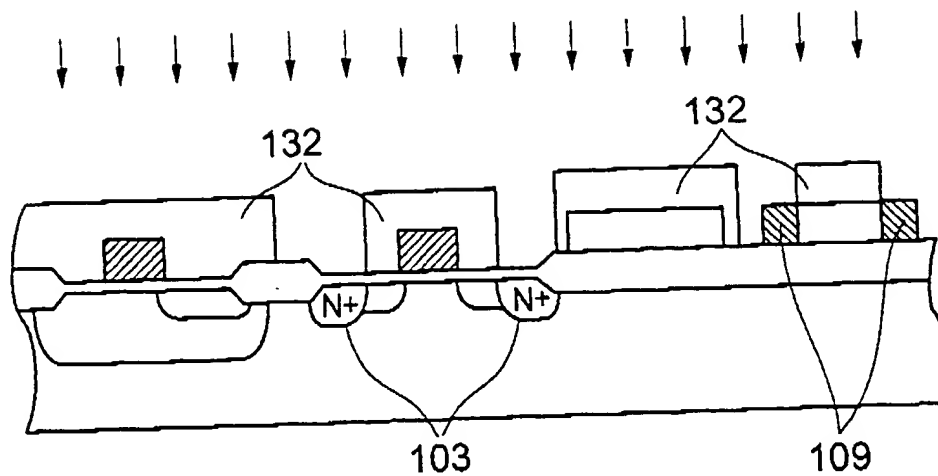


FIG.73

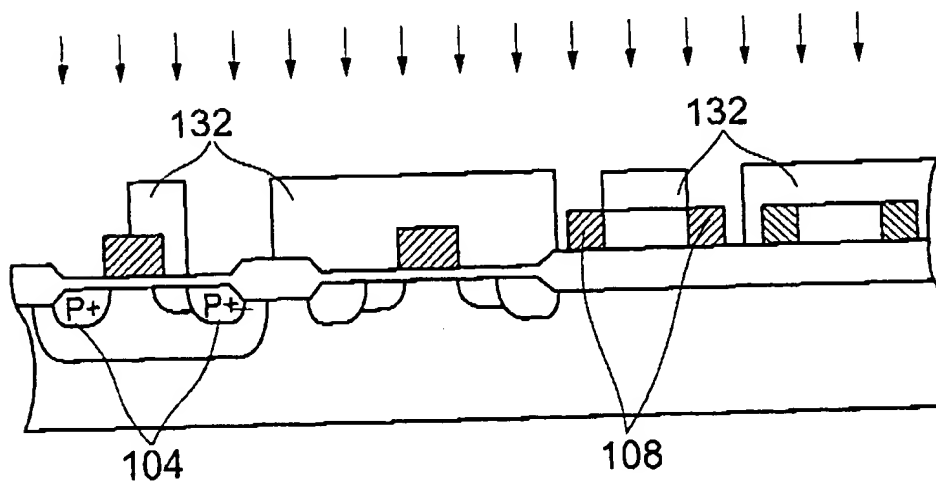


FIG.74

FIG. 73

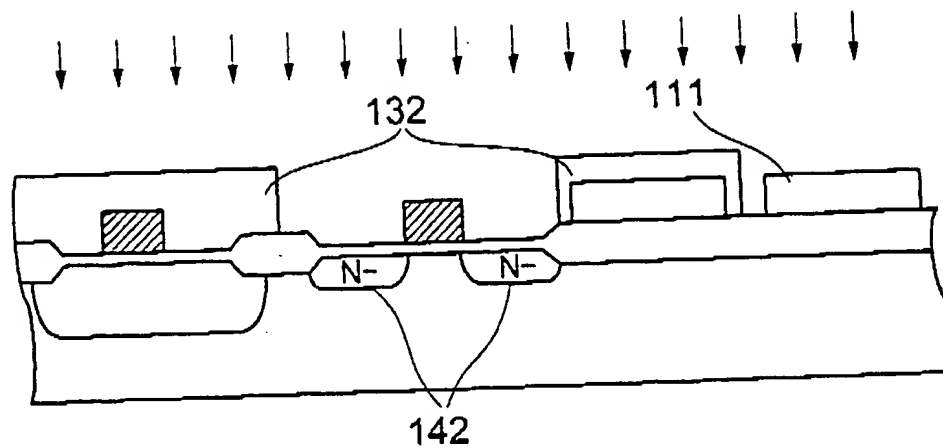


FIG.75

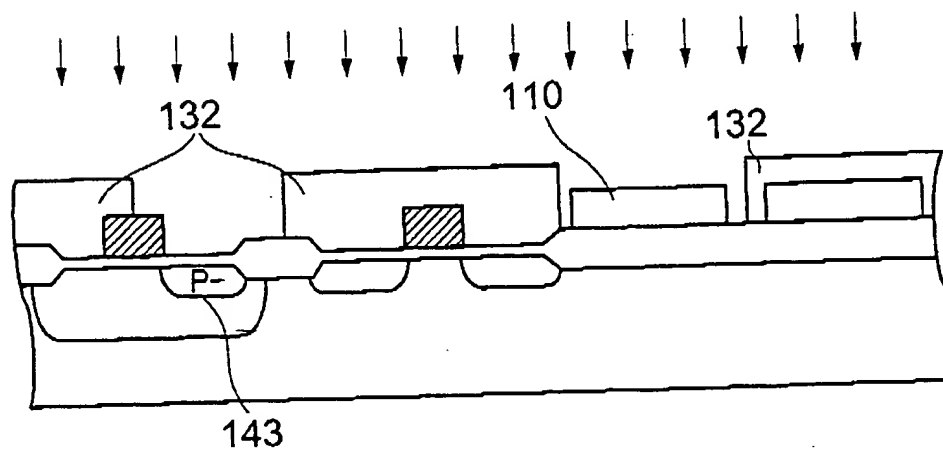


FIG.76

FIG. 75 is a cross-sectional diagram of a semiconductor device.

FIG. 77

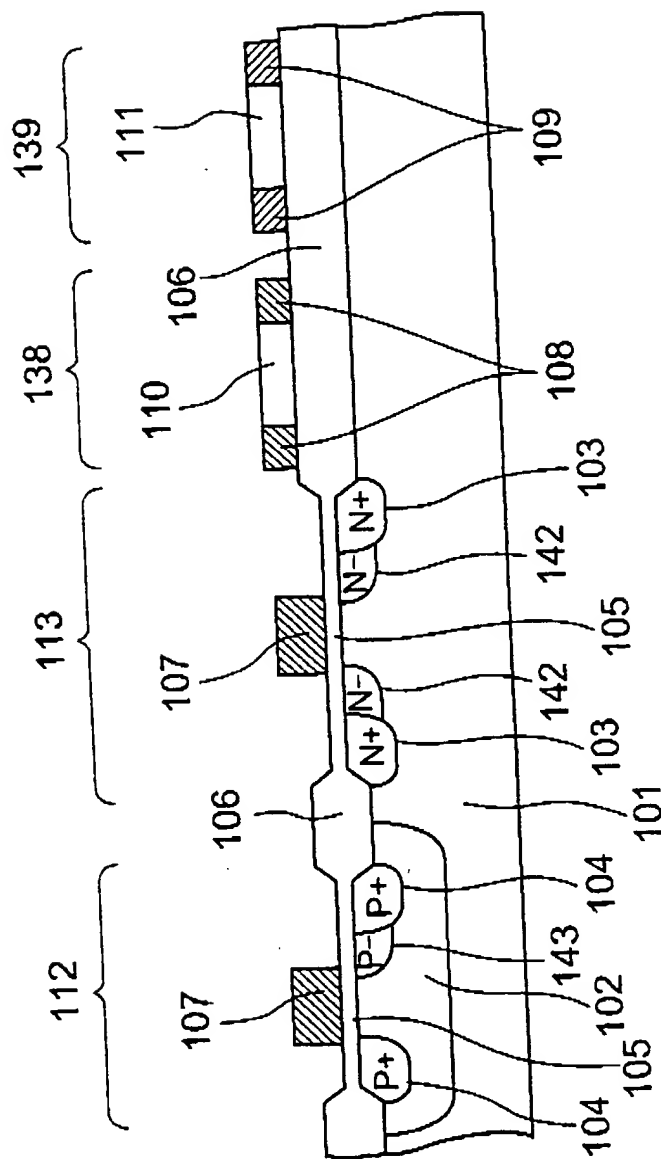


FIG. 77

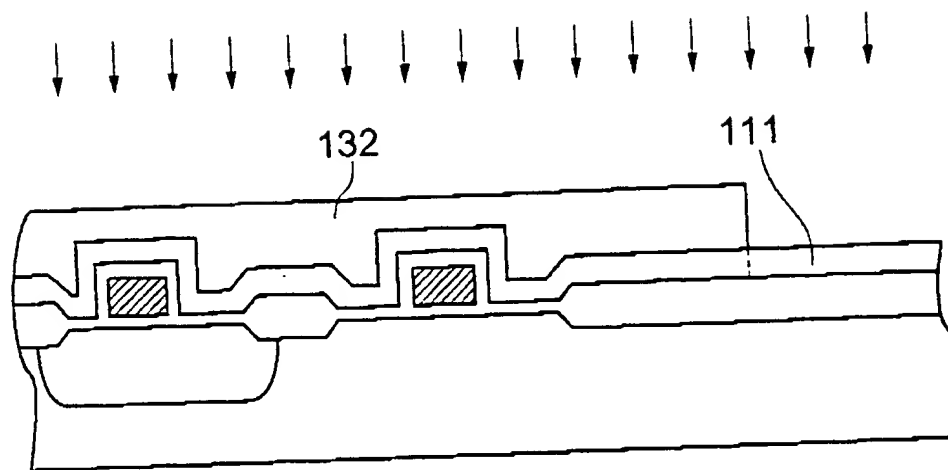


FIG.80

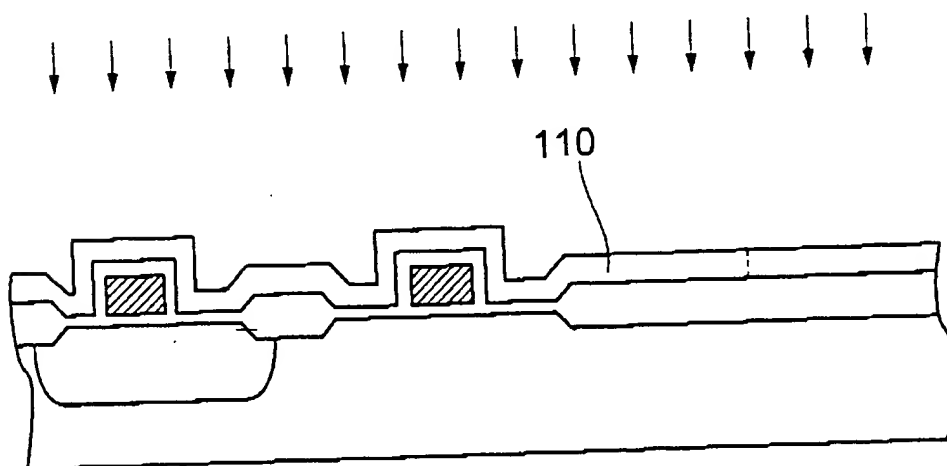


FIG.81

FIG. 80 is a cross-sectional view of the device structure.

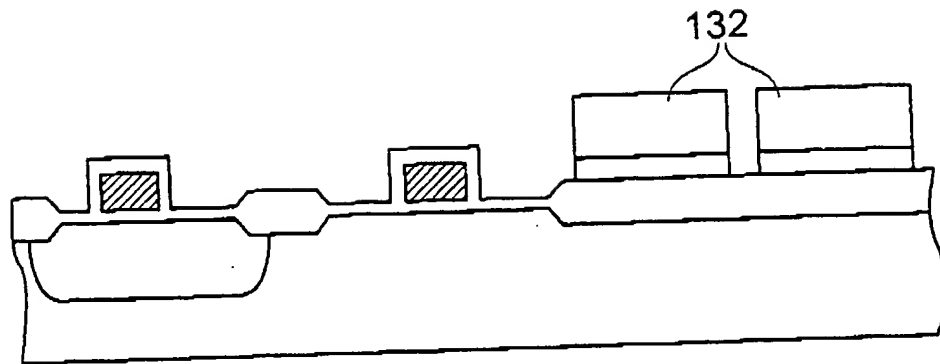


FIG.82

FIG. 82

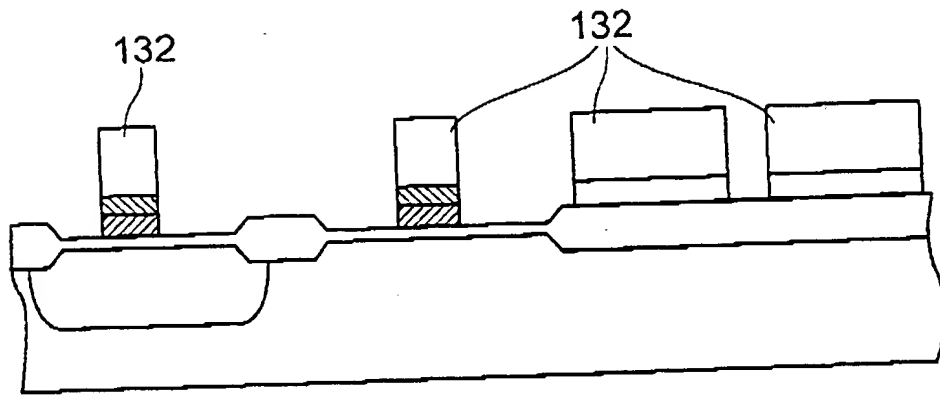


FIG.84

FIG. 84

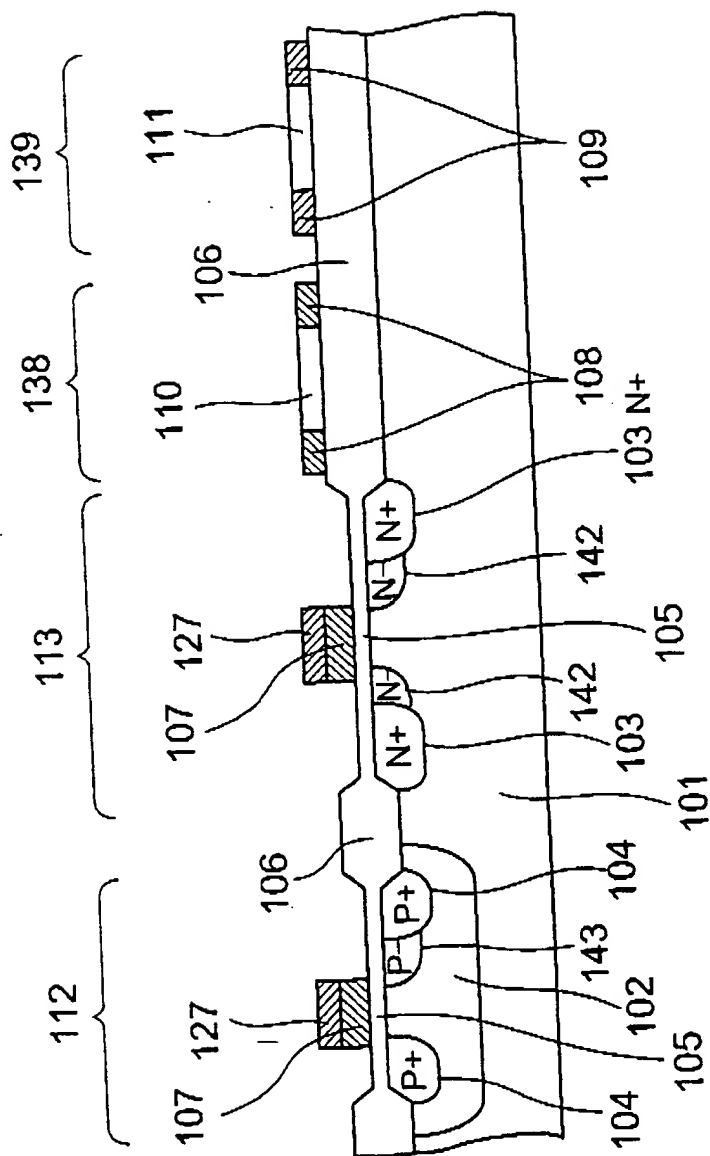
[illegible]

FIG. 85

FIG. 86

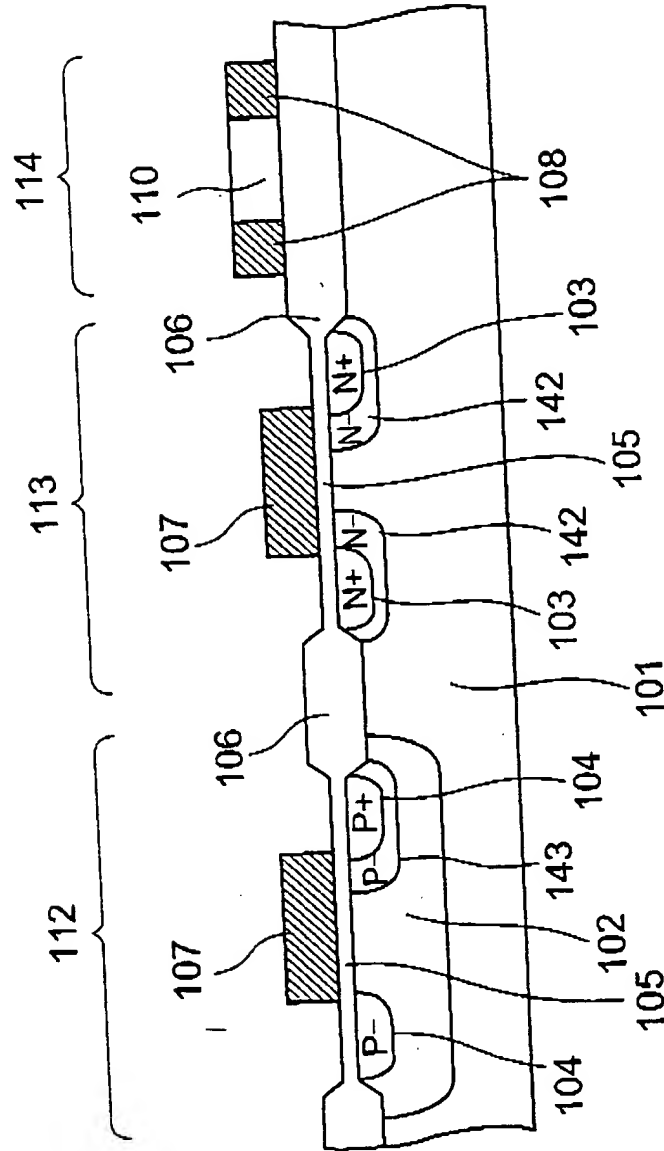


FIG. 86

FIG. 87

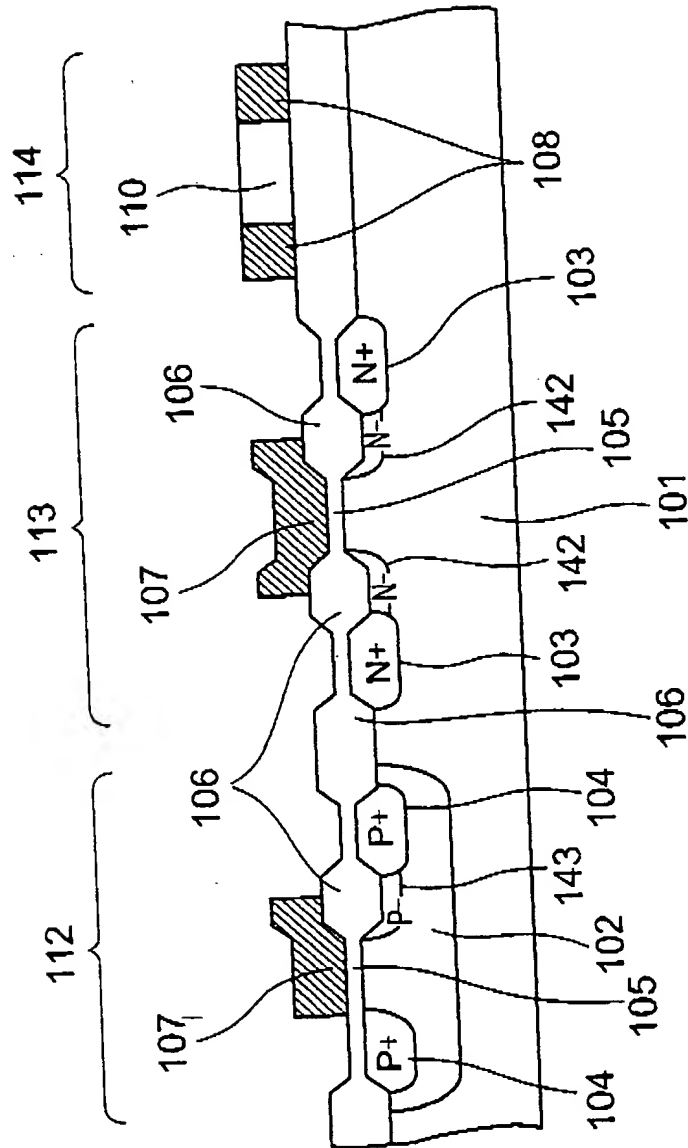


FIG.87

FIG. 88

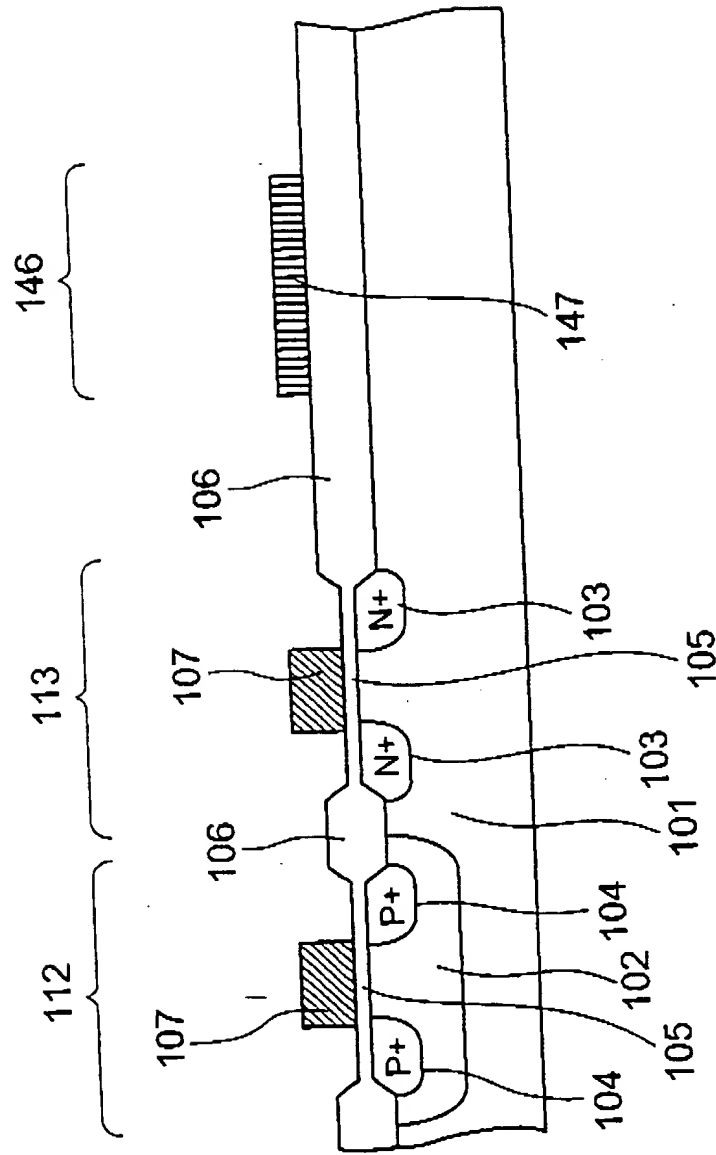


FIG. 88

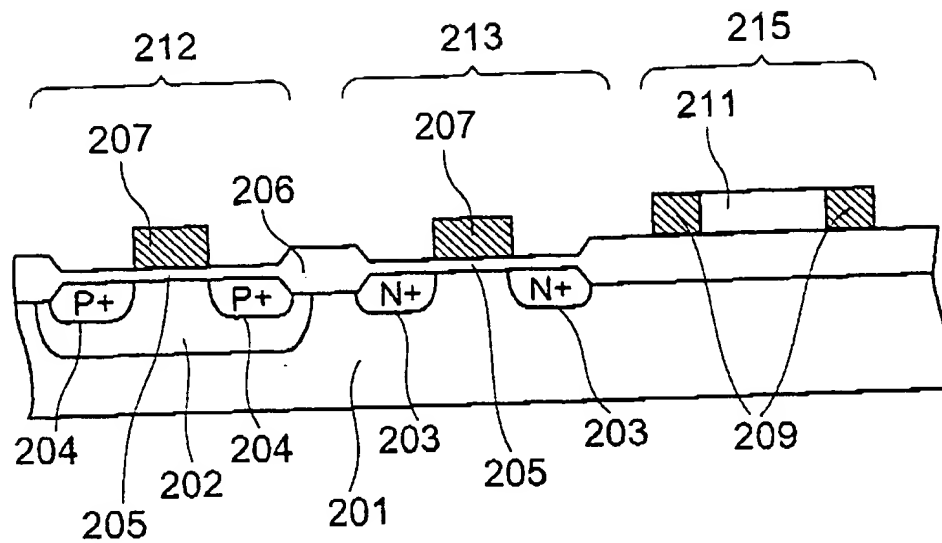


FIG. 89
PRIOR ART

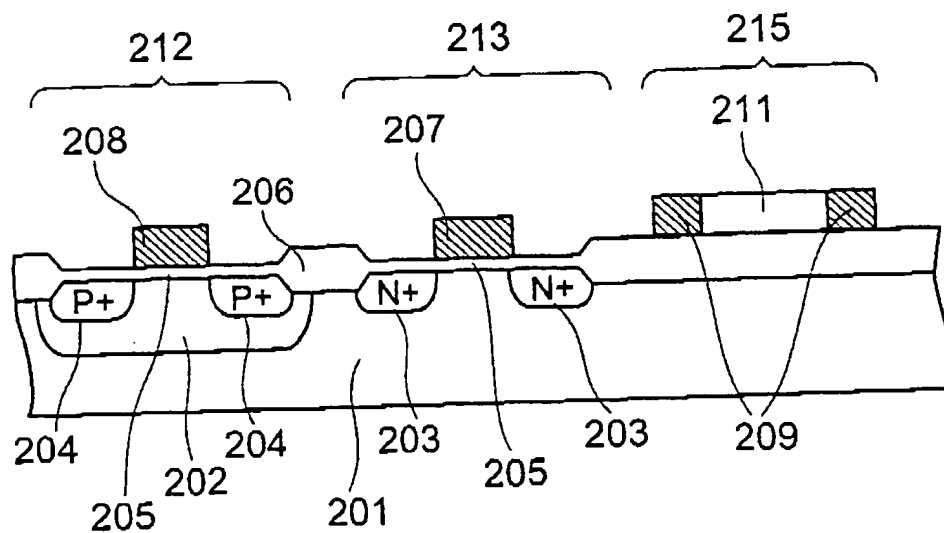


FIG. 90
PRIOR ART

FIG. 89

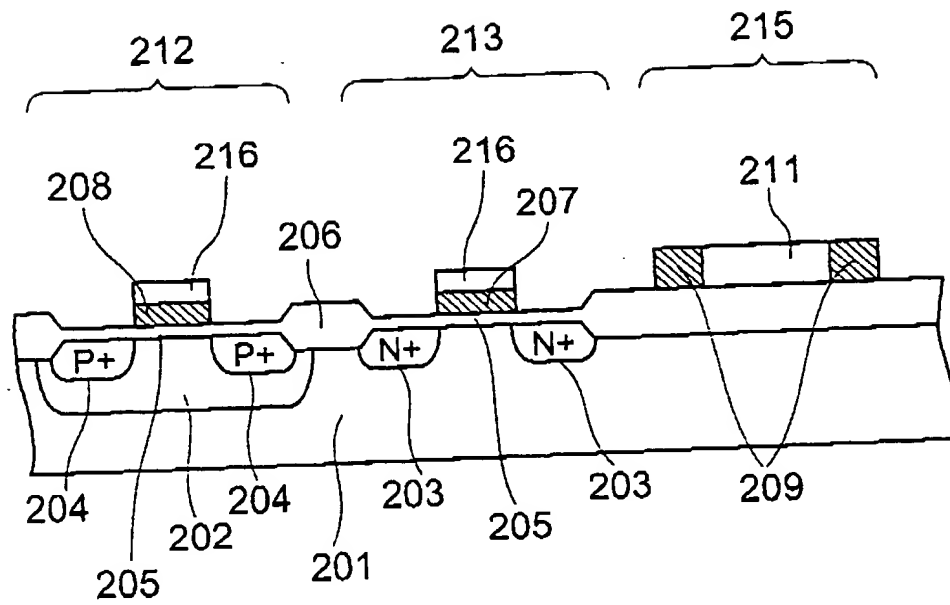


FIG.91
PRIOR ART